

Datasheet

BL654 Series

Version 2.8

REVISION HISTORY

Version	Date	Notes	Contributor(s)	Approver
1.0	24 June 2018	Initial Production Release	Raj Khatri	Jonathan Kaye
1.1	29 June 2018	Added certification and BT SIG information	Tom Smith	Jonathan Kaye
1.2	04 Sept 2018	Added new product photos; updated BT SIG and Ordering information	Sue White	Jonathan Kaye
1.3	20 Sept 2018	Corrected antenna type for FlexPIFA / FlexNotch in Table 25 .	Mark Wolski	Sue White
1.4	03 Oct 2018	Added note re: no support for Nordic SDK.	Rikki Horrigan	Jonathan Kaye
1.5	13 Nov 2018	Updated Standby Doze ram retention to 256k	Raj Khatri	Sue White
1.6	03 Dec 2018	Updated FCC and IC regulatory sections.	Tom Smith	Jonathan Kaye
1.7	03 Dec 2018	Updated Logos and URLs.	Emily Petropoulos	Jonathan Kaye
1.8	22 Mar 2019	Fixed pin 48 typo – A1 changed to A10	Rick Tretow	Jonathan Kaye
1.9	18 Sept 2019	Fixed PCB Antenna characteristics	Dave Drogowski	Jonathan Kaye
1.10	24 Oct 2019	Fixed errors in the Pin Definitions table – Comments for Pin 8 and Pin 28	Raj Khatri	Jonathan Kaye
1.11	04 Feb 2020	Updated BT to v5.1 from 5.0 Updated SIG information	Sue White	Jonathan Kaye
1.12	6 May 2020	Updated 4.2 Peripheral Block Current Consumption, tables10(UART), table11(SPI), table12(I2C), table 13(ADC) and added current consumption when operated from DCDC(REG1) and LDO(REG1).	Raj Khatri	Jonathan Kaye
1.13	20 May 2020	Fixed Tape and Reel information	Maggie Teng	Jonathan Kaye
1.14	10 Nov 2020	Added an additional Module Specification note	Henry Wagner	Jonathan Kaye
2.0	14 Dec 2020	Updated all regulatory information	Maggie Teng Ryan Urness	Jonathan Kaye
2.1	13 Jan 2021	Moved regulatory information to separate BL654 Regulatory Information document	Sue White	Jonathan Kaye
2.2	18 Feb 2021	Fixed equation in 5.5.2 NFC Antenna Coil Tuning Capacitors	Raj Khatri	Dave Drogowski
2.3	18 Aug 2021	Added section 12 Reliability Tests	Raj Khatri	Jonathan Kaye
2.4	10 Aug 2021	Updated Table 25 (removed unnecessary row)	Raj Khatri	Jonathan Kaye
2.5	22 Dec 2021	Updated Mechanical Details	Dave Drogowski	Andrew Chen
2.6	29 Nov 2022	Updated Bluetooth SIG Qualification with new QD ID.	Steve Flooks	Jonathan Kaye
2.7	14 Aug 2023	Updated Tape and Reel Package Information section	Robert Gosewehr	Dave Drogowski
2.8	11 Dec 2023	Updated On-board PCB Antenna Characteristics	Adam Engelbrecht	Dave Drogowski

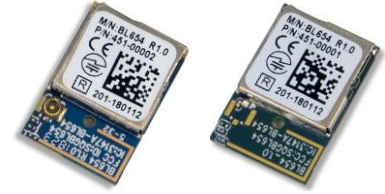
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1 OVERVIEW AND KEY FEATURES

Every BL654 Series module is designed to simplify OEMs enablement of Bluetooth Low Energy (BLE) v5.1 and Thread (802.15.4) to small, portable, power-conscious devices. The BL654 provides engineers with considerable design flexibility in both hardware and software programming capabilities. Based on the world-leading Nordic Semiconductor nRF52840 chipset, the BL654 modules provide ultra-low power consumption with outstanding wireless range via +8 dBm of transmit power and the Long Range (CODED PHY) Bluetooth 5 feature. The BL654 is programmable via Laird Connectivity's *smartBASIC* language or Nordic's software development kit (SDK).



smartBASIC is an event-driven programming language that is highly optimized for memory-constrained systems such as embedded modules. It was designed to make BLE development quicker and simpler, vastly cutting down time to market.

The Nordic SDK, on the other hand, offers developers source code (in C) and precompiled libraries containing BLE and ANT+ device profiles, wireless communication, as well as application examples.

Note: BL654 hardware provides all functionality of the nRF52840 chipset used in the module design. This is a hardware datasheet only – it does not cover the software aspects of the BL654.

For customers using *smartBASIC*, refer to the *smartBASIC* extensions guide (available from the [BL654 product page](#) of the Laird Connectivity website. For customers using the Nordic SDK, refer to www.nordicsemi.com.

Note: Nordic SDK is not supported on the BL654 USB dongle, part #451-00003.

1.1 Features and Benefits

- Bluetooth v5.1 – Single mode
- NFC
- 802.15.4 (Thread) radio support
- External or internal antennas
- Multiple programming options
 - *smartBASIC* AT command set shim or
 - Nordic SDK in C
- Compact footprint
- Programmable Tx power +8 dBm to -20 dBm, -40 dBm
- Rx sensitivity – -95 dBm (1 Mbps), - 103 dBm (125 kbps)
- Ultra-low power consumption
- Tx – 4.8 mA peak (at 0 dBm, DCDC on)
(See [Note 1](#) in the *Power Consumption* section)
- Rx: 4.6 mA peak (DCDC on)
(See [Note 1](#) in the *Power Consumption* section)
- Standby Doze – 3.1 uA typical
- Deep Sleep – 0.4 uA – (See [Note 4](#) in the *Power Consumption* section)
- UART, GPIO, ADC, PWM, FREQ output, timers, I2C, SPI, I2S, PDM, and USB interfaces
- Fast time-to-market
- FCC, EU, ISED, RCM and Japan certified
- Full Bluetooth Declaration ID
- Other regulatory certifications on request
- No external components required
- Industrial temperature range (-40° C to +85° C)

1.2 Application Areas

- Medical devices
- IoT Sensors
- Accessories
- Fitness sensors
- Location awareness
- Home automation

2 SPECIFICATION

2.1 Specification Summary

Categories/Feature	Implementation				
Wireless Specification					
Bluetooth®	<ul style="list-style-type: none"> BT 5.1 – Single mode 4x Range (CODED PHY support) – BT 5.1 2x Speed (2M PHY support) – BT 5.1 LE Advertising Extensions – BT 5.1 Concurrent master, slave BLE Mesh capabilities Diffie-Hellman based pairing (LE Secure Connections) – BT 4.2 Data Packet Length Extension – BT 4.2 Link Layer Privacy (LE Privacy 1.2) – BT 4.2 LE Dual Mode Topology – BT 4.1 LE Ping – BT 4.1 				
Frequency	2.402 - 2.480 GHz				
Raw Data Rates	1 Mbps BLE (over-the-air) 2 Mbps BLE (over-the-air) 125 kbps BLE (over-the-air) 500 kbps BLE (over-the-air)				
Maximum Transmit Power Setting <i>(See Note 1 in the Module Specification Notes)</i>	<table border="1"> <tr> <td>+8 dBm</td> <td>Conducted 451-00001 (Integrated antenna)</td> </tr> <tr> <td>+8 dBm</td> <td>Conducted 451-00002 (External antenna)</td> </tr> </table>	+8 dBm	Conducted 451-00001 (Integrated antenna)	+8 dBm	Conducted 451-00002 (External antenna)
+8 dBm	Conducted 451-00001 (Integrated antenna)				
+8 dBm	Conducted 451-00002 (External antenna)				
Minimum Transmit Power Setting	-40 dBm, -20 dBm (in 4 dB steps) -16 dBm, -12 dBm, - 8 dBm, - 4 dBm, 0 dBm, 2 dBm, 4 dBm, 5 dBm, 6 dBm, 7 dBm,				
Receive Sensitivity (≤37byte packet)	BLE 1 Mbps (BER=1E-3) -95 dBm typical				
	BLE 2 Mbps -92 dBm typical				
	BLE 125 kbps -103 dBm typical				
	BLE 500 kbps -99 dBm typical				
Link Budget (conducted)	103 dB @ BLE 1 Mbps				
	111 dB @ BLE 125 kbps				
NFC					
NFC-A Listen mode compliant	Based on NFC forum specification				
	<ul style="list-style-type: none"> 13.56 MHz Date rate 106 kbps NFC Type2 and Type 4 emulation 				
	Modes of Operation:				
	<ul style="list-style-type: none"> Disable Sense Activated 				
System Wake-On-Field function	Use Cases:				
	<ul style="list-style-type: none"> Touch-to-Pair with NFC NFC enabled Out-of-Band Pairing 				

Categories/Feature	Implementation
Host Interfaces and Peripherals	
Total	48 x multifunction I/O lines
UART	2 UARTs Tx, Rx, CTS, RTS DCD, RI, DTR, DSR (See Note 2 and Note 1 in the Module Specification Notes) Default 115200, n, 8, 1 From 1,200 bps to 1 Mbps
USB	USB 2.0 FS (Full Speed, 12Mbps). CDC driver / Virtual UART (baud rate TBD) Other USB drivers available via Nordic SDK
GPIO	Up to 48, with configurable: I/O direction, O/P drive strength (standard 0.5 mA or high 3mA/5 mA), Pull-up /pull-down Input buffer disconnect
ADC	Eight 8/10/12-bit channels 0.6 V internal reference Configurable 4, 2, 1, 1/2, 1/3, 1/4, 1/5 1/6(default) pre-scaling Configurable acquisition time 3uS, 5uS, 10uS (default), 15uS, 20uS, 40uS. One-shot mode
PWM Output	PWM outputs on 16 GPIO output pins. <ul style="list-style-type: none"> ▪ PWM output duty cycle: 0%-100% ▪ PWM output frequency: Up to 500kHz
FREQ Output	FREQ outputs on 16 GPIO output pins. <ul style="list-style-type: none"> ▪ FREQ output frequency: 0 MHz-4MHz (50% duty cycle)
I2C	Two I2C interface (up to 400 kbps) – See Note 3 in the Module Specification Notes
SPI	Four SPI Master Slave interface (up to 4 Mbps)
QSPI	One 32-MHz QSPI interface. Gives XIP (Execution in Place) capability. External serial flash IC must be fitted as per Nordic specifications.
Temperature Sensor	One temperature sensor. Temperature range equal to the operating temperature range. Resolution 0.25 degrees.
RSSI Detector	One RF received signal strength indicator ±2 dB accuracy (valid over -90 to -20 dBm) One dB resolution
I2S	One inter-IC sound interface
PDM	One pulse density modulation interface
Optional (External to the BL654 module)	
External 32.768 kHz crystal	For customer use, connect +/-20ppm accuracy crystal for more accurate protocol timing.

Categories/Feature	Implementation
Profiles	
Services supported	<ul style="list-style-type: none"> ▪ Central Mode ▪ Peripheral Mode ▪ Mesh (with custom models) ▪ Custom and adopted profiles
Programmability	
<i>smart</i> BASIC	FW upgrade via JTAG or UART Application download via UART or Via Over-the-Air (if SIO_02 pin is pulled high externally)
Nordic SDK	Via JTAG Note: Nordic SDK is not supported on the BL654 USB dongle, part #451-00003.
Operating Modes	
<i>smart</i> BASIC	Self-contained Run mode Selected by nAutoRun pin status: LOW (0V). Then runs \$autorun\$ (<i>smart</i> BASIC application script) if it exists. Interactive/Development mode HIGH (VDD). Then runs via at+run (and <i>file name</i> of <i>smart</i> BASIC application script).
Nordic SDK	As per Nordic SDK Note: Nordic SDK is not supported on the BL654 USB dongle, part #451-00003.
Supply Voltage	
Supply (VDD or VDD_HV) options	<ul style="list-style-type: none"> ▪ Normal voltage mode VDD 1.7- 3.6 V – Internal DCDC converter or LDO (See Note 4 in the Module Specification Notes) OR ▪ High voltage mode VDD_HV 2.5V-5.5V Internal DCDC converter or LDO (See Note 4 and Note 5 in the Module Specification Notes)

Power Consumption

Active Modes Peak Current (for maximum Tx power +8 dBm) – Radio only	14.8 mA peak Tx (with DCDC)
Active Modes Peak Current (for Tx power -40 dBm) – Radio only	4.6 mA peak Tx (with DCDC)
Active Modes Average Current	Depends on many factors, see Power Consumption section
Ultra-low Power Modes	Standby Doze 3.1 uA typical Deep Sleep 0.4 uA

Antenna Options

Internal	Printed PCB monopole antenna – on-board 451-00001 variant
External	<ul style="list-style-type: none"> ▪ Dipole antenna (with IPEX connector) ▪ Dipole PCB antenna (with IPEX connector) ▪ Connection via IPEX MH4 – 451-00002 variant <p>See the <i>External Antenna Integration with the 451-00002 sections</i> for FCC, ISED, MIC, RCM and EU.</p>

Physical

Dimensions	15.0 mm x 10 mm x 2.2 mm Pad Pitch – 0.8 mm Pad Type – Two rows of pads
Weight	<1 gram

Environmental

Operating	-40 °C to +85 °C
Storage	-40 °C to +85 °C

Miscellaneous

Lead Free	Lead-free and RoHS compliant
Warranty	One-Year Warranty

Development Tools

Development Kit	Development kit per module SKU (455-00001 and 455-00002) and free software tools
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Approvals

Bluetooth®	Full Bluetooth SIG Declaration ID
FCC/ISED/EU/MIC/RCM	All BL654 Series

Module Specification Notes:

Note 1	When used in IEEE 802.15.4 mode, 802.15.4 channel 26 must be limited to -8 dBm maximum transmit power to limit out of band emissions. All other 802.15.4 channels (11-25) may be used up to the maximum +8 dBm output power.
Note 2	DSR, DTR, RI, and DCD can be implemented in the <i>smartBASIC</i> application or through the Nordic SDK. Note: Nordic SDK is not supported on the BL654 USB dongle, part #451-00003.

Module Specification Notes:

Note 3	With I2C interface selected, pull-up resistors on I2C SDA and I2C SCL must be connected externally as per I2C standard.
Note 4	Use of the internal DCDC convertor or LDO is decided by the underlying BLE stack.
Note 5	Nordic Errata 197 and 202 related to the use of VDD_HV DCDC convertor, for details refer to http://infocenter.nordicsemi.com/pdf/nRF52840_Rev_1_Errata_v1.1.pdf . Nordic Errata 202 means no external current draw (from VDD pin) is allowed during power up and VDD_HV rise time (to 3V) is below one mS.

3 HARDWARE SPECIFICATIONS

3.1 Block Diagram and Pin-out

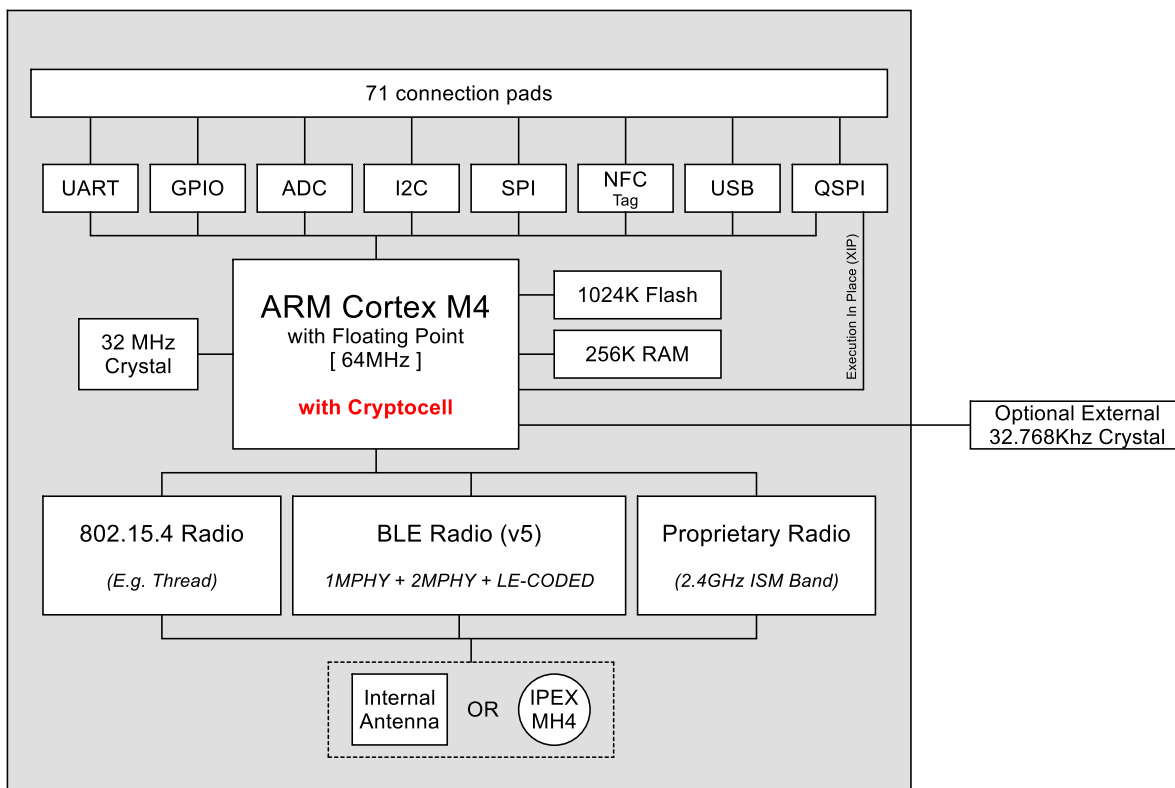


Figure 1: BL654 block diagram

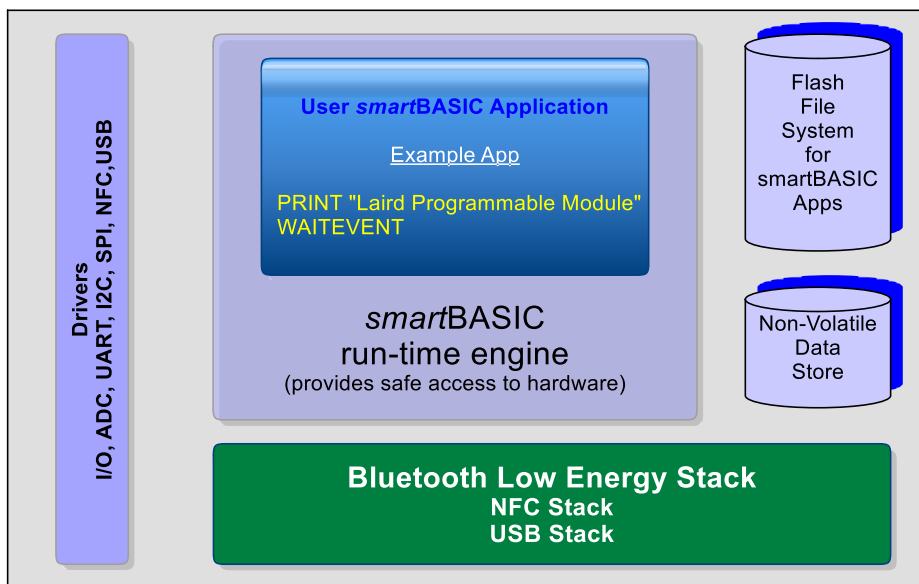


Figure 2: Functional HW and SW block diagram for BL654 series BLE module

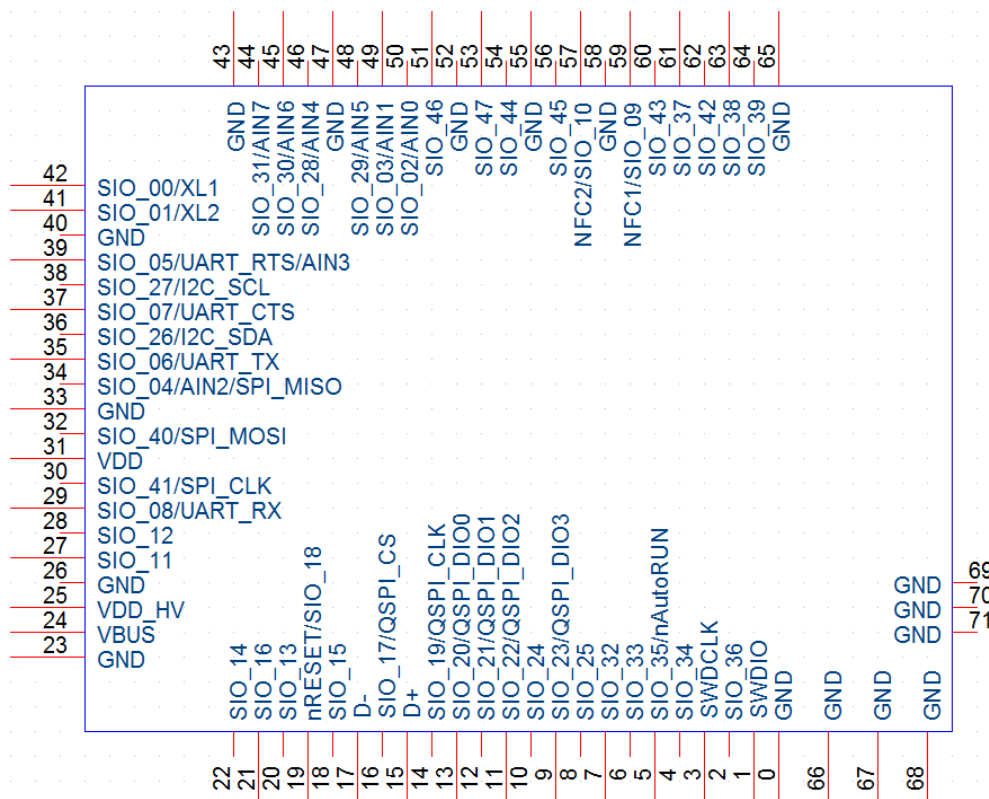


Figure 3: BL654 module pin-out (top view). Outer row pads (long red line) and inner row pads (short red line) shown.

3.2 Pin Definitions

Table 1: Pin definitions

Pin #	Pin Name	Default Function	Alternate Function	In/ Out	Pull Up/ Down	nRF52840 QFN Pin	nRF52840 QFN Name	Comment
0	GND	-	-	-	-	-	-	-
1	SWDIO	SWDIO	-	IN	PULL-UP	AC24	SWDIO	-
2	SIO_36	SIO_36	-	IN	PULL-UP	U24	P1.04	-
3	SWDCLK	SWDCLK	-	IN	PULL-DOWN	AA24	SWDCLK	-
4	SIO_34	SIO_34	-	-	PULL-UP	W24	P1.02	-
5	SIO_35/ nAutoRUN	nAutoRUN	SIO_35	IN	PULL-DOWN	V23	P1.03	Laird Devkit: FTDI USB_DTR via jumper on J12pin1-2.
6	SIO_33	SIO_33	-	IN	PULL-UP	Y23	P1.01	-
7	SIO_32	SIO_32	-	IN	PULL-UP	AD22	P1.00	-
8	SIO_25	SIO_25	-	IN	PULL-UP	AC21	PO.25	Laird Devkit: BUTTON4
9	SIO_23	SIO_23	QSPI_DIO3	IN	PULL-UP	AC19	PO.23	-
10	SIO_24	SIO_24	-	IN	PULL-UP	AD20	PO.24	Laird Devkit: BUTTON3
11	SIO_22	SIO_22	QSPI_DIO2	IN	PULL-UP	AD18	PO.22	-
12	SIO_21	SIO_21	QSPI_DIO1	IN	PULL-UP	AC17	PO.21	-
13	SIO_20	SIO_20	QSPI_DIO0	IN	PULL-UP	AD16	PO.20	-
14	SIO_19	SIO_19	QSPI_CLK	IN	PULL-UP	AC15	PO.19	-
15	D+	D+	-	IN	-	AD6	D+	-
16	SIO_17	SIO_17	QSPI_CS	IN	PULL-UP	AD12	PO.17	-
17	D-	D-	-	IN	-	AD4	D-	-
18	SIO_15	SIO_15	-	IN	PULL-UP	AD10	PO.15	Laird Devkit: LED3
19	nRESET	nRESET	SIO_18	IN	PULL-UP	AC13	PO.18	System Reset (Active Low)
20	SIO_13	SIO_13	-	IN	PULL-UP	AD8	PO.13	Laird Devkit: LED1
21	SIO_16	SIO_16	-	IN	PULL-UP	AC11	PO.16	Laird Devkit: LED4
22	SIO_14	SIO_14	-	IN	PULL-UP	AC9	PO.14	Laird Devkit: LED2

Pin #	Pin Name	Default Function	Alternate Function	In/Out	Pull Up/Down	nRF52840 QFN Pin	nRF52840 QFN Name	Comment
23	GND	-	-	-	-	-	-	-
24	VBUS							4.35V – 5.5V
25	VDD_HV	-	-	-	-	-	-	2.5V to 5.5V
26	GND	-	-	-	-	-	-	-
27	SIO_11	SIO_11	-	IN	PULL-UP	T2	PO.11	Laird Devkit: BUTTON1
28	SIO_12	SIO_12	-	IN	PULL-UP	U1	PO.12	BUTTON2
29	SIO_08/ UART_RX	SIO_08	UART_RX	IN	PULL-UP	N1	PO.08	UARTCLOSE() selects DIO functionality. UARTOPEN() selects UART COMMS behavior
30	SIO_41/ SPI_CLK	SIO_41	SPI_CLK	IN	PULL-UP	R1	P1.09	Laird Devkit: SPI EEPROM. SPI_Eeprom_CLK, Output: SPIOPEN() in <i>smartBASIC</i> selects SPI function, MOSI and CLK are outputs when in SPI master mode.
31	VDD	-	-	-	-			1.7V to 3.6V
32	SIO_40/ SPI_MOSI	SIO_40	SPI_MOSI	IN	PULL-UP	P2	P1.08	Laird Devkit: SPI EEPROM. SPI_Eeprom_MOSI, Output SPIOPEN() in <i>smartBASIC</i> selects SPI function, MOSI and CLK are outputs in SPI master.
33	GND	-	-	-	-	-	-	-
34	SIO_04/ AIN2/ SPI_MISO	SIO_04	AIN2/ SPI_MISO	IN	PULL-UP	J1	PO.04/AIN2	Laird Devkit: SPI EEPROM. SPI_Eeprom_MISO, Input. SPIOPEN() in <i>smartBASIC</i> selects SPI function; MOSI and CLK are outputs when in SPI master mode
35	SIO_06/ UART_TX	SIO_06	UART_TX	OUT	Set High in FW	L1	PO.06	UARTCLOSE() selects DIO functionality. UARTOPEN() selects UART COMMS behaviour

Pin #	Pin Name	Default Function	Alternate Function	In/Out	Pull Up/Down	nRF52840 QFN Pin	nRF52840 QFN Name	Comment
36	SIO_26/ I2C_SDA	SIO_26	I2C_SDA	IN	PULL-UP	G1	PO.26	Laird Devkit: I2C RTC chip. I2C data line.
37	SIO_07/ UART_CTS	SIO_07	UART_CTS	IN	PULL-DOWN	M2	PO.07	UARTCLOSE() selects DIO functionality. UARTOPEN() selects UART COMMS behaviour
38	SIO_27/ I2C_SCL	SIO_27	I2C_SCL	IN	PULL-UP	H2	PO.27	Laird Devkit: I2C RTC chip. I2C clock line.
39	SIO_05/ UART_RTS/ AIN3	SIO_05	UART_RTS/ AIN3	OUT	Set Low in FW	K2	PO.05/AIN3	UARTCLOSE() selects DIO functionality. UARTOPEN() selects UART COMMS behaviour
40	GND	-	-	-	-	-	-	-
41	SIO_01/ XL2	SIO_01	XL2	IN	PULL-UP	F2	PO.01/XL2	Laird Devkit: Optional 32.768kHz crystal pad XL2 and associated load capacitor.
42	SIO_00/ XL1	SIO_00	XL1	IN	PULL-UP	D2	PO.00/XL1	Laird Devkit: Optional 32.768kHz crystal pad XL1 and associated load capacitor.
43	GND	-	-	-	-	-	-	-
44	SIO_31/ AIN7	SIO_31	AIN7	IN	PULL-UP	A8	PO.31/AIN7	-
45	SIO_30/ AIN6	SIO_30	AIN6	IN	PULL-UP	B9	PO.30/AIN6	-
46	SIO_28/ AIN4	SIO_28	AIN4	IN	PULL-UP	B11	PO.28/AIN4	-
47	GND	-	-	-	-	-	-	-
48	SIO_29/ AIN5	SIO_29	AIN5	IN	PULL-UP	A10	PO.29/AIN5	-
49	SIO_03/ AIN1	SIO_03	AIN1	IN	PULL-UP	B13	PO.03/AIN1	Laird Devkit: Temp Sens Analog
50	SIO_02/ AIN0	SIO_02	AIN0	IN	PULL-DOWN	A12	PO.02/AIN0	Internal pull-down. Pull High externally to enter VSP (Virtual Serial Port) Service.
51	SIO_46	SIO_46	-	IN	PULL-UP	B15	P1.14	-
52	GND	-	-	-	-	-	-	-
53	SIO_47	SIO_47	-	IN	PULL-UP	A14	P1.15	-
54	SIO_44	SIO_44	-	IN	PULL-UP	B17	P1.12	Laird Devkit: SPI EEPROM.

Pin #	Pin Name	Default Function	Alternate Function	In/Out	Pull Up/Down	nRF52840 QFN Pin	nRF52840 QFN Name	Comment
								SPI_Eeprom_CS, Input
55	GND	-	-	-	-	-	-	-
56	SIO_45	SIO_45	-	IN	PULL-UP	A16	P1.13	-
57	NFC2/ SIO_10	NFC2	SIO_10	IN	-	J24	PO.10/NFC2	-
58	GND	-	-	-	-	-	-	-
59	NFC1/ SIO_09	NFC1	SIO_09	IN	-	L24	PO.09/NFC1	-
60	SIO_43	SIO_43	-	IN	PULL-UP	B19	P1.11	-
61	SIO_37	SIO_37	-	IN	PULL-UP	T23	P1.05	-
62	SIO_42	SIO_42	-	IN	PULL-UP	A20	P1.10	-
63	SIO_38	N/C	-	IN	PULL-UP	R24	P1.06	Reserved for future use. Do not connect.
64	SIO_39	SIO_39	-	IN	PULL-UP	P23	P1.07	-
65	GND	-	-	-	-	-	-	-
66	GND	-	-	-	-	-	-	-
67	GND	-	-	-	-	-	-	-
68	GND	-	-	-	-	-	-	-
69	GND	-	-	-	-	-	-	-
70	GND	-	-	-	-	-	-	-
71	GND	-	-	-	-	-	-	-

Pin Definition Notes:

Note 1	SIO = Signal Input or Output. Secondary function is selectable in <i>smartBASIC</i> application or via Nordic SDK. I/O voltage level tracks VDD. AIN = Analog Input.
Note 2	At reset, all SIO lines are configured as the defaults shown above. SIO lines can be configured through the <i>smartBASIC</i> application script to be either inputs or outputs with pull-ups or pull-downs. When an alternative SIO function is selected (such as I2C or SPI), the firmware does not allow the setup of internal pull-up/pull-down. Therefore, when I2C interface is selected, pull-up resistors on I2C SDA and I2C SCL must be connected externally as per I2C standard.
Note 3	JTAG (two-wire SWD interface), pin 1 (SWDIO) and pin 3 (SWDCLK). JTAG is required because Nordic SDK applications can only be loaded using JTAG (<i>smartBASIC</i> firmware can be loaded using the JTAG as well as UART). We recommend that you use JTAG (2-wire interface) to handle future BL654 module <i>smartBASIC</i> firmware upgrades. You MUST wire out the JTAG (2-wire interface) on your host design (see Figure 7 , where four lines (SWDIO, SWDCLK, GND and VDD) should be wired out. <i>smartBASIC</i> firmware upgrades can still be performed over the BL654 UART interface, but this is slower (60 seconds using UART vs. 10 seconds when using JTAG) than using the BL654 JTAG (2-wire interface). Upgrading <i>smartBASIC</i> firmware or loading the <i>smartBASIC</i> applications is done using the UART interface.
Note 4	Pull the nRESET pin (pin 19) low for minimum 100 milliseconds to reset the BL654.

Pin Definition Notes:

Note 5	The SIO_02 pin (pin 50) must be pulled high externally to enable VSP (Virtual Serial Port) which would allow OTA (over-the-air) <i>smartBASIC</i> application download. Refer to the latest firmware release documentation for details.
Note 6	Ensure that SIO_02 (pin 50) and AutoRUN (pin 5) are not both high (externally), in that state, the UART is bridged to Virtual Serial Port service; the BL654 module does not respond to AT commands and cannot load <i>smartBASIC</i> application scripts.
Note 7	<p>Pin 5 (nAutoRUN) is an input, with active low logic. In the development kit it is connected so that the state is driven by the host's DTR output line. The nAutoRUN pin must be externally held high or low to select between the following two BL654 operating modes:</p> <ul style="list-style-type: none"> ▪ Self-contained Run mode (nAutoRUN pin held at 0V –this is the default (internal pull-down enabled)) ▪ Interactive/Development mode (nAutoRUN pin held at VDD) <p>The <i>smartBASIC</i> firmware checks for the status of nAutoRUN during power-up or reset. If it is low and if there is a <i>smartBASIC</i> application script named \$autorun\$, then the <i>smartBASIC</i> firmware executes the application script automatically; hence the name <i>Self-contained Run Mode</i>.</p>
Note 8	<p>The <i>smartBASIC</i> firmware has SIO pins as Digital (Default Function) INPUT pins, which are set PULL-UP by default. This avoids floating inputs (which can cause current consumption to drive with time in low power modes (such as Standby Doze). You can disable the PULL-UP through your <i>smartBASIC</i> application.</p> <p>All of the SIO pins (with a default function of DIO) are inputs (apart from SIO_05 and SIO_06, which are outputs):</p> <ul style="list-style-type: none"> ▪ SIO_06 (alternative function UART_TX) is an output, set High (in the firmware). ▪ SIO_05 (alternative function UART_RTS) is an output, set Low (in the firmware). ▪ SIO_08 (alternative function UART_RX) is an input, set with internal pull-up (in the firmware). ▪ SIO_07 (alternative function UART_CTS) is an input, set with internal pull-down (in the firmware). ▪ SIO_02 is an input set with internal pull-down (in the firmware). It is used for OTA downloading of <i>smartBASIC</i> applications. Refer to the latest firmware extension documentation for details. ▪ UART_RX, UART_TX, and UART_CTS are 3.3 V level logic (if VDD is 3.3 V; such as SIO pin I/O levels track VDD). For example, when Rx and Tx are idle, they sit at 3.3 V (if VDD is 3.3 V). Conversely, handshaking pins CTS and RTS at 0V are treated as assertions.
Note 9	BL654 also allows as an option to connect an external higher accuracy (± 20 ppm) 32.768 kHz crystal to the BL654 pins SIO_01/XL2 (pin 41) and SIO_00/XL1 (pin 42). This provides higher accuracy protocol timing and helps with radio power consumption in the system standby doze/deep sleep modes by reducing the time that the Rx window must be open.
Note 10	<p>Not required for BL654 module normal operation. The on-chip 32.768kHz LFRC oscillator provides the standard accuracy of ± 500 ppm, with calibration required every 8seconds (default) to stay within ± 500 ppm.</p> <p>BL654 power supply options:</p> <ul style="list-style-type: none"> ▪ Option 1 – Normal voltage power supply mode entered when the external supply voltage is connected to both the VDD and VDD_HV pins (so that VDD equals VDD_HV). Connect external supply within range 1.7V to 3.6V range to BL654 VDD and VDD_HV pins. <p>OR</p> <ul style="list-style-type: none"> ▪ Option 2 – High voltage mode power supply mode (using BL654 VDD_HV pin) entered when the external supply voltage in ONLY connected to the VDDH pin and the VDD pin is not connected to any external voltage supply. Connect external supply within range 2.5V to 5.5V range to BL654 VDD_HV pin. BL654 VDD pin left unconnected. <p>Nordic Errata 197 and 202 related to the use of VDD_HV DCDC convertor, for details refer to http://infocenter.nordicsemi.com/pdf/nRF52840_Rev_1_Errata_v1.1.pdf. Nordic Errata 202 means no external current draw (from VDD pin) is allowed during power up and VDD_HV rise time (to 3V) is below one millisecond.</p> <ul style="list-style-type: none"> ▪ For either option, if you use USB interface then the BL654 VBUS pin must be connected to external supply within the range 4.35V to 5.5V. When using the BL654 VBUS pin, you MUST externally fit a 4.7uF to ground.

3.3 Electrical Specifications

3.3.1 Absolute Maximum Ratings

Absolute maximum ratings for supply voltage and voltages on digital and analogue pins of the module are listed below; exceeding these values causes permanent damage.

Table 2: Maximum current ratings

Parameter	Min	Max	Unit
Voltage at VDD pin	-0.3	+3.9 (Note 1)	V
Voltage at VDD_HV pin	-0.3	+5.8	V
VBUS	-0.3	+5.8	V
Voltage at GND pin		0	V
Voltage at SIO pin (at VDD ≤ 3.6V)	-0.3	VDD + 0.3	V
Voltage at SIO pin (at VDD ≥ 3.6V)	-0.3	3.9	V
NFC antenna pin current (NFC1/2)	-	80	mA
Radio RF input level	-	10	dBm

Environmental

Storage temperature	-40	+85	°C
MSL (Moisture Sensitivity Level)	-	4	-
ESD (as per EN301-489)			
Conductive		4	KV
Air Coupling		8	KV
Flash Memory (Endurance) (Note 2)	-	10000	Write/erase cycles
Flash Memory (Retention)	-	10 years at 40 °C	-

Maximum Ratings Notes:

Note 1	The absolute maximum rating for VDD_nRF pin (max) is 3.9V for the BL654.
Note 2	Wear levelling is used in file system.

3.3.2 Recommended Operating Parameters

Table 3: Power supply operating parameters

Parameter	Min	Typ	Max	Unit
VDD (independent of DCDC) ¹ supply range	1.7	3.3	3.6	V
VDD_HV (independent of DCDC) supply range	2.5	3.7	5.5	V
VBUS USB supply range	4.35	5	5.5	V
VDD Maximum ripple or noise ²	-	-	10	mV
VDD supply rise time (0V to 1.7V) ³	-	-	60	mS
Time in Power				mS
				mS
				mS
VDD_HV supply rise time (0V to 3.7V) ³			100	mS
Operating Temperature Range	-40	-	+85	°C

Recommended Operating Parameters Notes:

Note 1	4.7 uF internal to module on VDD. The internal DCDC convertor or LDO is decided by the underlying BLE stack.
Note 2	This is the maximum VDD or VDD_HV ripple or noise (at any frequency) that does not disturb the radio.
Note 3	The on-board power-on reset circuitry may not function properly for rise times longer than the specified maximum.
Note 4	<p>BL654 power supply options:</p> <ul style="list-style-type: none"> ▪ Option 1 – Normal voltage power supply mode entered when the external supply voltage is connected to both the VDD and VDD_HV pins (so that VDD equals VDD_HV). Connect external supply within range 1.7V to 3.6V range to BL654 VDD and VDD_HV pins. <p>OR</p> <ul style="list-style-type: none"> ▪ Option 2 – High voltage mode power supply mode (using BL654 VDD_HV pin) entered when the external supply voltage is ONLY connected to the VDD_HV pin and the VDD pin is not connected to any external voltage supply. Connect external supply within range 2.5V to 5.5V range to BL654 VDD_HV pin. BL654 VDD pin left unconnected. <p>Nordic Errata 197 and 202 related to the use of VDD_HV DCDC convertor, for details refer to http://infocenter.nordicsemi.com/pdf/nRF52840_Rev_1_Errata_v1.1.pdf. Nordic Errata 202 means no external current draw (from VDD pin) is allowed during power up and VDD_HV rise time (to 3V) is below 1 millisecond.</p> <ul style="list-style-type: none"> ▪ For either option, if you use USB interface then the BL654 VBUS pin must be connected to external supply within the range 4.35V to 5.5V. When using the BL654 VBUS pin, you MUST externally fit a 4.7uF to ground.

Table 4: Signal levels for interface, SIO

Parameter	Min	Typ	Max	Unit
V _{IH} Input high voltage	0.7 VDD		VDD	V
V _{IL} Input low voltage	VSS		0.3 x VDD	V
V _{OH} Output high voltage				
(std. drive, 0.5mA) (Note 1)	VDD -0.4		VDD	V
(high-drive, 3mA) (Note 1)	VDD -0.4		VDD	V
(high-drive, 5mA) (Note 2)	VDD -0.4		VDD	
V _{OL} Output low voltage				
(std. drive, 0.5mA) (Note 1)	VSS		VSS+0.4	V
(high-drive, 3mA) (Note 1)	VSS		VSS+0.4	V
(high-drive, 5mA) (Note 2)	VSS		VSS+0.4	
V _{OL} Current at VSS+0.4V, Output set low				
(std. drive, 0.5mA) (Note 1)	1	2	4	mA
(high-drive, 3mA) (Note 1)	3	-	-	mA
(high-drive, 5mA) (Note 2)	6	10	15	mA
V _{OL} Current at VDD -0.4, Output set low				
(std. drive, 0.5mA) (Note 1)	1	2	4	mA
(high-drive, 3mA) (Note 1)	3	-	-	mA
(high-drive, 5mA) (Note 2)	6	9	14	mA
Pull up resistance	11	13	16	kΩ
Pull down resistance	11	13	16	kΩ
Pad capacitance		3		pF

Parameter	Min	Typ	Max	Unit
Pad capacitance at NFC pads		4		pF

Signal Levels Notes:

- Note 1** For $VDD \geq 1.7V$. The firmware supports high drive (3 mA, as well as standard drive).
- Note 2** For $VDD \geq 2.7V$. The firmware supports high drive (5 mA (since $VDD \geq 2.7V$), as well as standard drive).
- The GPIO (SIO) high reference voltage always equals the level on the **VDD** pin.
- Normal voltage mode – The GPIO high level equals the voltage supplied to the VDD pin
 - High voltage mode – The GPIO high level equals the level specified (is configurable to 1.8V, 2.1V, 2.4V, 2.7V, 3.0V, and 3.3V. The default voltage is 1.8V). In High voltage mode, the VDD pin becomes an output voltage pin. The VDD output voltage and hence the GPIO is configurable from 1.8V to 3.3V with possible settings of 1.8V, 2.1V, 2.4V, 2.7V, 3.0V, and 3.3V. Refer to [Table 15](#) for additional details.

Table 5: SIO pin alternative function AIN (ADC) specification

Parameter	Min	Typ	Max	Unit
Maximum sample rate			200	kHz
ADC Internal reference voltage	-1.5%	0.6 V	+1.5%	%
ADC pin input internal selectable scaling		4, 2, 1, 1/2, 1/3, 1/4, 1/5, 1/6		scaling
ADC input pin (AIN) voltage maximum without damaging ADC w.r.t (see Note 1)				
VCC Prescaling	0V-VDD	4, 2, 1, 1/2, 1/3, 1/4, 1/5, 1/6	VDD+0.3	V
Configurable Resolution	8-bit mode	10-bit mode	12-bit mode	bits
Configurable (see Note 2)				
Acquisition Time, source resistance $\leq 10k\Omega$		3		μS
Acquisition Time, source resistance $\leq 40k\Omega$		5		μS
Acquisition Time, source resistance $\leq 100k\Omega$		10		μS
Acquisition Time, source resistance $\leq 200k\Omega$		15		μS
Acquisition Time, source resistance $\leq 400k\Omega$		20		μS
Acquisition Time, source resistance $\leq 800k\Omega$		40		μS
Conversion Time (see Note 3)		<2		μS
ADC input impedance (during operation) (see Note 3)				
Input Resistance		>1		MOhm
Sample and hold capacitance at maximum gain		2.5		pF

Recommended Operating Parameters Notes:

- Note 1** Stay within internal 0.6 V reference voltage with given pre-scaling on AIN pin and do not violate ADC maximum input voltage (for damage) for a given VCC, e.g. If VDD is 3.6V, you can only expose AIN pin to VDD+0.3 V. Default pre-scaling is 1/6 which configurable via smartBASIC.

Recommended Operating Parameters Notes:

Note 2	<p>Firmware allows configurable resolution (8-bit, 10-bit or 12-bit mode) and acquisition time. BL654 ADC is a Successive Approximation type ADC (SSADC), as a result no external capacitor is needed for ADC operation. Configure the acquisition time according to the source resistance that customer has.</p> <p>The sampling frequency is limited by the sum of sampling time and acquisition time. The maximum sampling time is 2us. For acquisition time of 3us the total conversion time is therefore 5us, which makes maximum sampling frequency of $1/5\mu s = 200\text{kHz}$. Similarly, if acquisition time of 40us chosen, then the conversion time is 42us and the maximum sampling frequency is $1/42\mu s = 23.8\text{kHz}$.</p>
Note 3	ADC input impedance is estimated mean impedance of the ADC (AIN) pins.

3.4 Programmability

3.4.1 BL654 Default Firmware

The BL654 module comes loaded with *smartBASIC* firmware but does not come loaded with any *smartBASIC* application script (as that is dependent on customer-end application or use). Laird Connectivity provides many sample *smartBASIC* application scripts via a sample application folder on GitHub – <https://github.com/LairdCP/BL654-Applications>

Therefore, it boots into AT command mode by default.

3.4.1 BL654 Special Function Pins in *smartBASIC*

Refer to the *smartBASIC* extension manual for details of functionality connected to this:

- nAutoRUN pin (SIO_35), see Table 6 for default
- VSP pin (SIO_02), see Table 7 for default
- SIO_38 – Reserved for future use. Do not connect. See Table 8

Table 6: nAutoRUN pin

Signal Name	Pin #	I/O	Comments
nAutoRUN /(SIO_35)	5	I	<p>Input with active low logic. Internal pull down (default).</p> <p>Operating mode selected by nAutoRun pin status:</p> <ul style="list-style-type: none"> ▪ Self-contained Run mode (nAutoRUN pin held at 0V). ▪ If Low (0V), runs \$autorun\$ if it exists ▪ Interactive/Development mode (nAutoRUN pin held at VCC). ▪ If High (VCC), runs via at+run (and file name of application)

In the development board nAutoRUN pin is connected so that the state is driven by the host's DTR output line.

Table 7: VSP mode

Signal Name	Pin #	I/O	Comments
SIO_02	50	I	<p>Internal pull down (default).</p> <p>VSP mode selected by externally pulling-up SIO_02 pin: High (VCC), then OTA <i>smartBASIC</i> application download is possible.</p>

Table 8: SIO_38

Signal Name	Pin #	I/O	Comments
SIO_38	63	I	<p>Internal pull up (default).</p> <p>Reserved for future use. Do not connect if using <i>smartBASIC</i> FW.</p>

4 POWER CONSUMPTION

Data at VDD of 3.3 V with internal (to chipset) LDO ON or with internal (to chipset) DCDC ON (see Power Consumption [Note 1](#)) and 25°C.

4.1 Power Consumption

Table 9: Power consumption

Parameter	Min	Typ	Max	Unit
Active mode 'peak' current (Note 1) (Advertising or Connection)		With DCDC [with LDO]		
Tx only run peak current @ Txpwr = +8 dBm		14.8 [32.7]		mA
Tx only run peak current @ Txpwr = +4 dBm		9.6 [21.4]		mA
Tx only run peak current @ Txpwr = 0 dBm		4.8 [10.6]		mA
Tx only run peak current @ Txpwr = -4 dBm		3.1 [8.1]		mA
Tx only run peak current @ Txpwr = -8 dBm		3.3 [7.2]		mA
Tx only run peak current @ Txpwr = -12 dBm		3.0 [6.4]		mA
Tx only run peak current @ Txpwr = -16 dBm		2.8 [6.0]		mA
Tx only run peak current @ Txpwr = -20 dBm		2.7 [5.6]		mA
Tx only run peak current @ Txpwr = -40 dBm		2.3 [4.6]		mA
Active Mode				
Rx only 'peak' current, BLE 1Mbps (Note 1)		4.6 [9.9]		mA
Rx only 'peak' current, BLE 2Mbps (Note 2)		5.2 [11.1]		mA
Ultra-Low Power Mode 1 (Note 2)				
Standby Doze, 256k RAM retention		3.1		uA
Ultra-Low Power Mode 2 (Note 3)				
Deep Sleep (no RAM retention)		0.4		uA
Active Mode Average current (Note 4)				
Advertising Average Current draw				
Max, with advertising interval (min) 20 mS		Note4		uA
Min, with advertising interval (max) 10240 mS		Note4		uA
Connection Average Current draw				
Max, with connection interval (min) 7.5 mS		Note4		uA
Min, with connection interval (max) 4000 mS		Note4		uA

Power Consumption Notes:

Note 1	This is for Peak Radio Current only, but there is additional current due to the MCU. The internal DCDC convertor or LDO is decided by the underlying BLE stack.
Note 2	BL654 modules Standby Doze is 3.1 uA typical. When using <i>smartBASIC</i> firmware, Standby Doze is entered automatically (when a waitevent statement is encountered within a <i>smartBASIC</i> application script). In Standby Doze, all peripherals that are enabled stay on and may re-awaken the chip. Depending on active peripherals, current consumption ranges from 3.1 uA to 370 uA (when UART is ON). See individual peripherals current consumption data in the Peripheral Block Current Consumption section. <i>smartBASIC</i> firmware has functionality to detect GPIO change with no current consumption cost, it is possible to close the UART and get to the 3.1 uA current consumption regime and still be able to

Power Consumption Notes:

	<p>detect for incoming data and be woken up so that the UART can be re-opened at expense of losing that first character.</p> <p>The BL654 Standby Doze current consists of the below nRF52840 blocks:</p> <ul style="list-style-type: none"> ▪ nRF52 System ON IDLE current (no RAM retention) (0.7 uA) – This is the base current of the CPU ▪ LFRC (0.7 uA) and RTC (0.1uA) running as well as 256k RAM retention (1.4 uA) – This adds to the total of 3.1 uA typical. The RAM retention is 20nA per 4k block, but this can vary to 30nA per 4k block which would make the total 3.7uA.
<p>Note 3</p>	<p>In Deep Sleep, everything is disabled and the only wake-up sources (including NFC to wakeup) are reset and changes on SIO or NFC pins on which sense is enabled. The current consumption seen is ~0.4 uA typical in BL654 modules.</p> <ul style="list-style-type: none"> ▪ Coming out from Deep Sleep to Standby Doze through the reset vector.
<p>Note 4</p>	<p>Average current consumption depends on several factors (including Tx power, VCC, accuracy of 32MHz and 32.768 kHz). With these factors fixed, the largest variable is the advertising or connection interval set.</p> <p>Advertising Interval range:</p> <ul style="list-style-type: none"> ▪ 20 milliseconds to 10240 mS (10485759.375 mS in BT 5.1) in multiples of 0.625 milliseconds. <p>For an advertising event:</p> <ul style="list-style-type: none"> ▪ The minimum average current consumption is when the advertising interval is large 10240 mS (10485759.375 mS in BT 5.1) although this may cause long discover times (for the advertising event) by scanners ▪ The maximum average current consumption is when the advertising interval is small 20 mS <p>Other factors that are also related to average current consumption include the advertising payload bytes in each advertising packet and whether it's continuously advertising or periodically advertising.</p> <p>Connection Interval range (for a peripheral):</p> <ul style="list-style-type: none"> ▪ 7.5 milliseconds to 4000 milliseconds in multiples of 1.25 milliseconds. <p>For a connection event (for a peripheral device):</p> <ul style="list-style-type: none"> ▪ The minimum average current consumption is when the connection interval is large 4000 milliseconds ▪ The maximum average current consumption is with the shortest connection interval of 7.5 ms; no slave latency. <p>Other factors that are also related to average current consumption include:</p> <ul style="list-style-type: none"> ▪ Number packets per connection interval with each packet payload size ▪ An inaccurate 32.768 kHz master clock accuracy would increase the average current consumption. <p>Connection Interval range (for a central device):</p> <ul style="list-style-type: none"> ▪ 2.5 milliseconds to 40959375 milliseconds in multiples of 1.25 milliseconds.

4.2 Peripheral Block Current Consumption

The values below are calculated for a typical operating voltage of 3V.

Table 10: UART power consumption

Parameter	Min	Typ		Max	Unit
		WITH DCDC(REG1)	WITH LDO(REG1)		
UART Run current @ 115200 bps	-	729	951	-	uA
UART Run current @ 1200 bps	-	729	951	-	uA
Idle current for UART (no activity)	-	29	29	-	uA
UART Baud rate	1.2	-	-	1000	kbps

Table 11: SPI power consumption

Parameter	Min	Typ		Max	Unit
		WITHDCDC(REG1)	WITH LDO(REG1)		
SPI Master Run current @ 2 Mbps	-	803	1040	-	uA
SPI Master Run current @ 8 Mbps	-	803	1040	-	uA
Idle current for SPI (no activity)	-	<1	<1	-	uA
SPI bit rate	-	-	-	8	Mbps

Table 12: I2C power consumption

Parameter	Min	Typ		Max	Unit
		WITH DCDC(REG1)	WITH LDO(REG1)		
I2C Run current @ 100 kbps	-	967	1250	-	uA
I2C Run current @ 400 kbps	-	967	1250	-	uA
Idle current for I2C (no activity)	-	3.2	3.2	-	uA
I2C Bit rate	100	-	-	400	kbps

Table 13: ADC power consumption

Parameter	Min	Typ		Max	Unit
		WITH DCDC(REG1)	WITH LDO(REG1)		
ADC current during conversion	-	1640	2010	-	uA
Idle current for ADC (no activity)	-	0	0	-	uA

The above current consumption is for the given peripheral including the internal blocks that are needed for that peripheral for both the case when DCDC(REG1) is on and off. The peripheral Idle current is when the peripheral is enabled but not running (not sending data or being used) and must be added to the StandByDoze current (Nordic System ON Idle current). In all cases radio is not turned on.

For asynchronous interface, like the UART (asynchronous as the other end can communicate at any time), the UART on the BL654 must be kept open (by a command in *smartBASIC* application script), resulting in the base current consumption penalty.

For a synchronous interface like the I2C or SPI (since BL654 side is the master), the interface can be closed and opened (by a command in *smartBASIC* application script) only when needed, resulting in current saving (no base current consumption penalty). There's a similar argument for ADC (open ADC when needed).

5 FUNCTIONAL DESCRIPTION

To provide the widest scope for integration, a variety of physical host interfaces/sensors are provided. The major BL654 series module functional blocks described below.

5.1 Power Management

Power management features:

- System Standby Doze and Deep Sleep modes
- Open/Close peripherals (UART, SPI, QSPI, I2C, SIO's, ADC, NFC). Peripherals consume current when open; each peripheral can be individually closed to save power consumption
- Use of the internal DCDC convertor or LDO is decided by the underlying BLE stack
- *smartBASIC* command allows the supply voltage to be read (through the internal ADC)
- Pin wake-up system from deep sleep (including from NFC pins)

Power supply features:

- Supervisor hardware to manage power during reset, brownout, or power fail.
- 1.7V to 3.6V supply range for normal power supply (VDD pin) using internal DCDC convertor or LDO decided by the underlying BLE stack.
- 2.5V to 5.5 supply range for High voltage power supply (VDD_HV pin) using internal DCDC convertor or LDO decided by the underlying BLE stack.
- 4.35V to 5.5V supply range for powering USB (VBUS pin) portion of BL654 only. The remainder of the BL654 module circuitry must still be powered through the VDD (or VDD_HV) pin.

5.2 BL654 Power Supply Options

The BL654 module power supply internally contains the following two main supply regulator stages (Figure 4):

- REG0 – Connected to the VDD_HV pin
- REG1 – Connected to the VDD pin

The USB power supply is separate (connected to the VBUS pin).

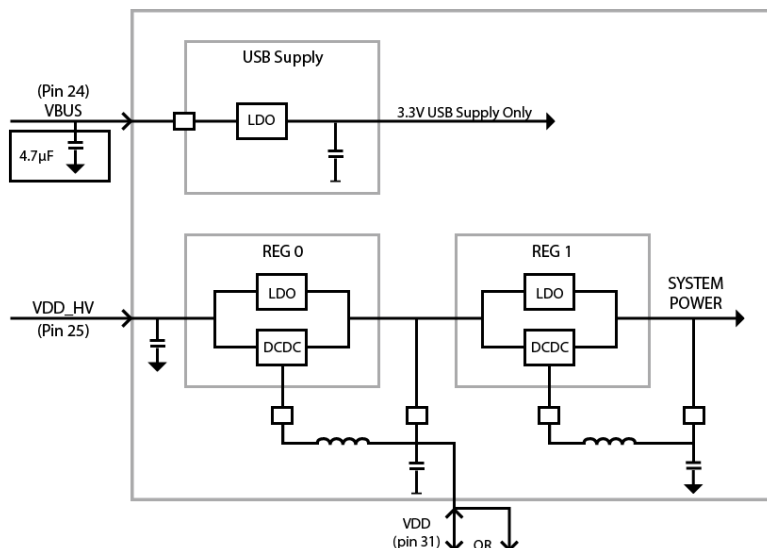


Figure 4: BL654 power supply block diagram (adapted from the following resource: http://infocenter.nordicsemi.com/pdf/nRF52840_PS_v1.0.pdf)

The BL654 power supply system enters one of two supply voltage modes, normal or high voltage mode, depending on how the external supply voltage is connected to these pins.

BL654 power supply options:

- **Option 1** – Normal voltage power supply mode entered when the external supply voltage is connected to both the VDD and VDD_HV pins (so that VDD equals VDD_HV). Connect external supply within range 1.7V to 3.6V range to BL654 VDD and VDD_HV pins.

OR

- **Option 2** – High voltage mode power supply mode (using BL654 VDD_HV pin) entered when the external supply voltage is ONLY connected to the VDD_HV pin and the VDD pin is not connected to any external voltage supply. Connect external supply within range 2.5V to 5.5V range to BL654 VDD_HV pin. BL654 VDD pin left unconnected.

Nordic Errata 197 and 202 related to the use of VDD_HV DCDC convertor, for details refer to http://infocenter.nordicsemi.com/pdf/nRF52840_Rev_1_Errata_v1.1.pdf. Nordic Errata 202 means no external current draw (from VDD pin) is allowed during power up and VDD_HV rise time (to 3V) is below 1mS.

For either option, if you use USB interface then the BL654 VBUS pin must be connected to external supply within the range 4.35V to 5.5V. When using the BL654 VBUS pin, you **MUST** externally fit a 4.7uF to ground.

Table 14 summarizes these power supply options.

Table 14: BL654 powering options

Power Supply Pins and Operating Voltage Range	OPTION1 Normal voltage mode operation connect?	OPTION2 High voltage mode operation connect?	OPTION1 with USB peripheral, operation, and normal voltage connect?	OPTION2 with USB peripheral, operation, and high voltage connect?
VDD (pin31) 1.7V to 3.6V	Yes (Note 1)	No (Note 2)	Yes	No (Note 2)
VDD_HV (pin25) 2.5V to 5.5V	No	Yes	No	Yes (Note 5)
VBUS (pin24) 4.35V to 5.5V	No	(Note 3)	Yes (Note 4)	Yes (Note 4)

Power Supply Option Notes:

Note 1	<p>Option 1 – External supply voltage is connected to BOTH the VDD and VDD_HV pins (so that VDD equals VDD_HV). Connect external supply within range 1.7V to 3.6V range to BOTH BL654 VDD and VDD_HV pins.</p>															
Note 2	<p>Option 2 – External supply within range 2.5V to 5.5V range to the BL654 VDD_HV pin ONLY. BL654 VDD pin left unconnected.</p> <p>In High voltage mode, the VDD pin becomes an output voltage pin. It can be used to supply external circuitry from the VDD pin. Before any current can be taken from the BL654 VDD pin, this feature must be enabled in the BL654. Additionally, the VDD output voltage is configurable from 1.8V to 3.3V with possible settings of 1.8V, 2.1V, 2.4V, 2.7V, 3.0V, and 3.3V. The default voltage is 1.8V.</p> <p>The supported BL654 VDD pin output voltage range depends on the supply voltage provided on the BL654 VDD_HV pin. The minimum difference between voltage supplied on the VDD_HV pin and the voltage output on the VDD pin is 0.3 V. The maximum output voltage of the VDD pin is $VDDH - 0.3V$. Table4 shows the current that can be drawn by external circuitry from VDD pin in high voltage mode (supply on VDD_HV).</p> <p>Table 15: Current that can be drawn by external circuitry from VDD pin in High voltage mode (supply on VDD_HV)</p> <table border="1"> <thead> <tr> <th>Parameter</th> <th>Min</th> <th>Typ</th> <th>Max</th> <th>Unit</th> </tr> </thead> <tbody> <tr> <td>External current draw (from VDD pin) allowed in High Voltage mode (supply on VDD_HV) during System OFF (BL654 Deep Sleep)</td> <td></td> <td></td> <td>1</td> <td>mA</td> </tr> <tr> <td>External current draw (from VDD pin) allowed in High Voltage mode (supply on VDD_HV) when radio Tx RF power higher than 4dBm.</td> <td></td> <td></td> <td>5</td> <td>mA</td> </tr> </tbody> </table>	Parameter	Min	Typ	Max	Unit	External current draw (from VDD pin) allowed in High Voltage mode (supply on VDD_HV) during System OFF (BL654 Deep Sleep)			1	mA	External current draw (from VDD pin) allowed in High Voltage mode (supply on VDD_HV) when radio Tx RF power higher than 4dBm.			5	mA
Parameter	Min	Typ	Max	Unit												
External current draw (from VDD pin) allowed in High Voltage mode (supply on VDD_HV) during System OFF (BL654 Deep Sleep)			1	mA												
External current draw (from VDD pin) allowed in High Voltage mode (supply on VDD_HV) when radio Tx RF power higher than 4dBm.			5	mA												

Power Supply Option Notes:

	External current draw (from VDD pin) allowed in High Voltage mode (supply on VDD_HV) when radio Tx RF power lower than 4dBm.	25	mA
	Minimum difference between voltage supplied on VDD_HV pin and voltage on VDD pin	0.3	V
Note 3	External current draw is the sum of all GPIO currents and current being drawn from VDD. Depends on whether USB operation is required		
Note 4	When using the BL654 VBUS pin, you must externally fit a 4.7uF capacitor to ground.		
Note 5	<p>To use the BL654 USB peripheral:</p> <ol style="list-style-type: none"> 1. Connect the BL654 VBUS pin to the external supply within the range 4.35V to 5.5V. When using the BL654 VBUS pin, you MUST externally fit a 4.7uF to ground. 2. Connect the external supply to either the VDD (Option 1) or VDD_HV (Option 2) pin to operate the rest of BL654 module. <p>When using the BL654 USB peripheral, the VBUS pin can be supplied from same source as VDD_HV (within the operating voltage range of the VBUS pin and VDD_HV pin).</p>		

5.3 Clocks and Timers

5.3.1 Clocks

The integrated high accuracy 32 MHz (± 10 ppm) crystal oscillator helps with radio operation and reducing power consumption in the active modes.

The integrated on-chip 32.768 kHz LFRC oscillator (± 500 ppm) provides protocol timing and helps with radio power consumption in the system StandByDoze and Deep Sleep modes by reducing the time that the RX window needs to be open.

To keep the on-chip 32.768 kHz LFRC oscillator within ± 500 ppm (which is needed to run the BLE stack) accuracy, RC oscillator needs to be calibrated (which takes 33 mS) regularly. The default calibration interval is eight seconds which is enough to keep within ± 500 ppm. The calibration interval ranges from 0.25 seconds to 31.75 seconds (in multiples of 0.25 seconds) and configurable via firmware.

5.3.2 Timers

When using *smartBASIC*, the timer subsystem enables applications to be written which allow future events to be generated based on timeouts.

- **Regular Timer** – There are eight built-in timers (regular timers) derived from a single RTC clock which are controlled solely by *smartBASIC* functions. The resolution of the regular timer is 976 microseconds.
- **Tick Timer** – A 31-bit free running counter that increments every (1) millisecond. The resolution of this counter is 488 microseconds.

Refer to the **smartBASIC User Guide** available from the Laird Connectivity BL654 product page. For timer utilization when using the Nordic SDK, refer to <http://infocenter.nordicsemi.com/index.jsp>.

Note: Nordic SDK is not supported on the BL654 USB dongle, part #451-00003.

5.4 Radio Frequency (RF)

- 2402–2480 MHz Bluetooth Low Energy radio BT 5.1 – 1 Mbps, 2 Mbps, and Long-range (125 kbps and 500 kbps) over-the-air data rate.
- Tx output power of +8 dBm programmable down to 7 dBm, 6 dBm, 5 dBm, 4 dBm, 2 dBm, 0 dBm and further down to -20 dBm in steps of 4 dB and final TX power level of -40 dBm.
- Receiver (with integrated channel filters) to achieve maximum sensitivity -95 dBm @ 1 Mbps BLE, -92 dBm @2 Mbps, -103 dBm @ 125 kbps long-range and -99 dBm @500kbps long-range).
- RF conducted interface available in the following two ways:
 - 451-00001: RF connected to on-board PCB trace antenna
 - 451-00002: RF connected to on-board IPEX MH4 RF connector
- Antenna options:
 - Integrated PCB trace antenna on the 451-00001
 - External dipole antenna connected with to IPEX MH4 RF connector on the 451-00002
- Received Signal Strength Indicator (RSSI)
- RSSI accuracy (valid range -90 to -20dBm) is ± 2 dB typical
- RSSI resolution 1dB typical

5.5 NFC

NFC support:

- Based on the NFC forum specification
 - 13.56 MHz
 - Data rate 106 kbps
 - NFC Type2 and Type4 tag emulation
- Modes of operation:
 - Disable
 - Sense
 - Activated

5.5.1 Use Cases

- Touch-to Pair with NFC
- Launch a smartphone app (on Android)
- NFC enabled Out-of-Band Pairing
- System Wake-On-Field function
 - Proximity Detection

Table 16: NFC interface

Signal Name	Pin No	I/O	Comments
NFC1/SIO_09	59	I/O	The NFC pins are by default NFC pins and an alternate function on each pin is GPIO. Refer to the <i>smartBASIC</i> . User manual.
NFC2/SIO_10	57	I/O	

5.5.2 NFC Antenna Coil Tuning Capacitors

From Nordic's *nRF52840 Objective Product Specification v1.0*: http://infocenter.nordicsemi.com/pdf/nRF52840_PS_v1.0.pdf

The NFC antenna coil must be connected differential between the NFC1 and NFC2 pins of the BL654. Two external capacitors should be used to tune the resonance of the antenna circuit to 13.56 MHz (Figure 5).

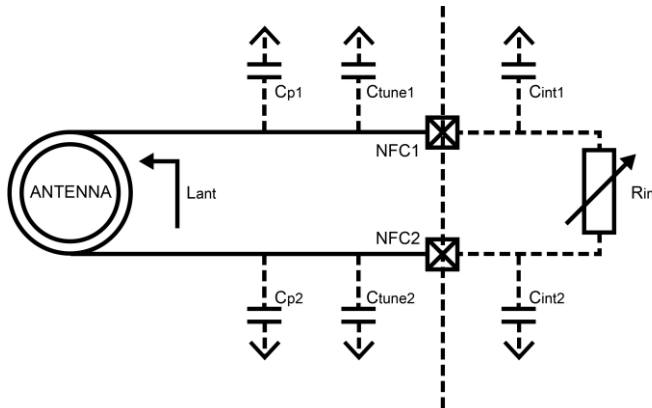


Figure 5: NFC antenna coil tuning capacitors

The required external tuning capacitor value is given by the following equations:

$$C_{tune} = \frac{2}{(2\pi \cdot 13.56 \text{ MHz})^2 \cdot L_{ant}} - C_p - C_{int}$$

An antenna inductance of $L_{ant} = 0.72 \text{ uH}$ provides tuning capacitors in the range of 300 pF on each pin. The total capacitance on NFC1 and NFC2 must be matched. C_{int} and C_p are small usually (C_{int} is 4pF), so can omit from calculation.

Battery Protection Note: If the NFC coil antenna is exposed to a strong NFC field, the supply current may flow in the opposite direction due to parasitic diodes and ESD structures.

If the used battery does not tolerate a return current, a series diode must be placed between the battery and the BL654 to protect the battery.

5.6 UART Interface

Note: The BL654 has two UARTs.

The Universal Asynchronous Receiver/Transmitter (UART) offers fast, full-duplex, asynchronous serial communication with built-in flow control support (UART_CTS, UART_RTS) in HW up to one Mbps baud. Parity checking and generation for the ninth data bit are supported.

UART_TX, UART_RX, UART_RTS, and UART_CTS form a conventional asynchronous serial data port with handshaking. The interface is designed to operate correctly when connected to other UART devices such as the 16550A. The signaling levels are nominal 0 V and 3.3 V (tracks VDD) and are inverted with respect to the signaling on an RS232 cable.

Two-way hardware flow control is implemented by UART_RTS and UART_CTS. UART_RTS is an output and UART_CTS is an input. Both are active low.

These signals operate according to normal industry convention. UART_RX, UART_TX, UART_CTS, UART_RTS are all 3.3 V level logic (tracks VDD). For example, when RX and TX are idle they sit at 3.3 V. Conversely for handshaking pins CTS, RTS at 0 V is treated as an assertion.

The module communicates with the customer application using the following signals:

- Port/TxD of the application sends data to the module's UART_RX signal line
- Port/RxD of the application receives data from the module's UART_TX signal line

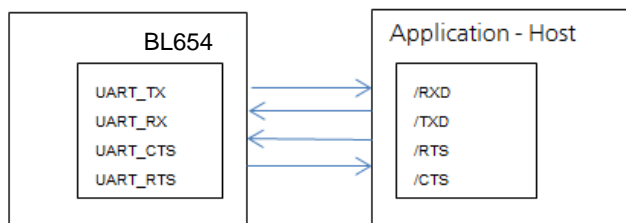


Figure 6: UART signals

Note: The BL654 serial module output is at 3.3V CMOS logic levels (tracks VDD). Level conversion must be added to interface with an RS-232 level compliant interface.

Some serial implementations link CTS and RTS to remove the need for handshaking. We do not recommend linking CTS and RTS other than for testing and prototyping. If these pins are linked and the host sends data at the point that the BL654 deasserts its RTS signal, there is significant risk that internal receive buffers will overflow, which could lead to an internal processor crash. This will drop the connection and may require a power cycle to reset the module. We recommend that the correct CTS/RTS handshaking protocol be adhered to for proper operation.

Table 17: UART interface

Signal Name	Pin No	I/O	Comments
SIO_06 / UART_Tx	35	O	SIO_06 (alternative function UART_Tx) is an output, set high (in firmware).
SIO_08 / UART_Rx	29	I	SIO_08 (alternative function UART_Rx) is an input, set with internal pull-up (in firmware).
SIO_05 / UART_RTS	39	O	SIO_05 (alternative function UART_RTS) is an output, set low (in firmware).
SIO_07 / UART_CTS	37	I	SIO_07 (alternative function UART_CTS) is an input, set with internal pull-down (in firmware).

The UART interface is also used to load customer developed *smartBASIC* application script.

5.7 USB interface

BL654 has USB2.0 FS (Full Speed, 12Mbps) hardware capability. There is a CDC driver/Virtual UART as well as other USB drivers available via Nordic SDK – such as: `usb_audio`, `usb_hid`, `usb_generic`, `usb_msc` (mass storage device).

Note: Nordic SDK is not supported on the BL654 USB dongle, part #451-00003.

Table 18: USB interface

Signal Name	Pin No	I/O	Comments
D-	17	I/O	
D+	15	I/O	
VBUS	24		When using the BL654 VBUS pin (which is mandatory when USB interface is used), Customer MUST connect externally a 4.7uF capacitor to ground. Note: You MUST power the rest of BL654 module circuitry through the VDD pin (OPTION1) or VDD_HV pin (OPTION2).

5.8 SPI Bus

The SPI interface is an alternate function on SIO pins.

The module is a master device that uses terminals SPI_MOSI, SPI_MISO, and SPI_CLK. SPI_CS is implemented using any spare SIO digital output pins to allow for multi-dropping.

The SPI interface enables full duplex synchronous communication between devices. It supports a 3-wire (SPI_MOSI, SPI_MISO, SPI_SCK,) bidirectional bus with fast data transfers to and from multiple slaves. Individual chip select signals are necessary for each of the slave devices attached to a bus, but control of these is left to the application through use of SIO signals. I/O data is double-buffered.

The SPI peripheral supports SPI mode 0, 1, 2, and 3.

Table 19: SPI interfaces

Signal Name	Pin No	I/O	Comments
SIO_40/SPI_MOSI	32	O	This interface is an alternate function configurable by <i>smartBASIC</i> . Default in the FW pin 56 and 53 are SIO inputs. SPIOPEN() in <i>smartBASIC</i> selects SPI function and changes pin 56 and 53 to outputs (when in SPI master mode).
SIO_04/AIN2/SPI_MISO	34	I	
SIO_41/SPI_CLK	30	O	
Any_SIO/SPI_CS	54	I	SPI_CS is implemented using any spare SIO digital output pins to allow for multi-dropping. On Laird Connectivity devboard SIO_44 (pin54) used as SPI_CS.

5.9 I2C Interface

The I2C interface is an alternate function on SIO pins.

The two-wire interface can interface a bi-directional wired-OR bus with two lines (SCL, SDA) and has master /slave topology. The interface is capable of clock stretching. Data rates of 100 kbps and 400 kbps are supported.

An I2C interface allows multiple masters and slaves to communicate over a shared wired-OR type bus consisting of two lines which normally sit at VDD. The SCL is the clock line which is always sourced by the master and SDA is a bi-directional data line which can be driven by any device on the bus.

IMPORTANT: It is essential to remember that pull-up resistors on both SCL and SDA lines are not provided in the module and MUST be provided external to the module.

Table 20: I2C interface

Signal Name	Pin No	I/O	Comments
SIO_26/I2C_SDA	36	I/O	This interface is an alternate function on each pin, configurable by <i>smartBASIC</i> . I2COPEN() function in <i>smartBASIC</i> selects I2C function.
SIO_27/I2C_SCL	38	I/O	

5.10 General Purpose I/O, ADC, PWM and FREQ

5.10.1 GPIO

The 19 SIO pins are configurable by *smartBASIC* application script or Nordic SDK. They can be accessed individually. Each has the following user configured features:

- Input/output direction
- Output drive strength (standard drive 0.5 mA or high drive 5mA)
- Internal pull-up and pull-down resistors (13 K typical) or no pull-up/down or input buffer disconnect
- Wake-up from high or low-level triggers on all pins including NFC pins

5.10.2 ADC

The ADC is an alternate function on SIO pins, configurable by *smartBASIC* or Nordic SDK.

The BL654 provides access to 8-channel 8/10/12-bit successive approximation ADC in one-shot mode. This enables sampling up to 8 external signals through a front-end MUX. The ADC has configurable input and reference pre-scaling and sample resolution (8, 10, and 12 bit).

5.10.2.1 Analog Interface (ADC)

Table 21: Analog interface

Signal Name	Pin No	I/O	Comments
SIO_05/UART_RTSAIN3 – Analog Input	39	I	This interface is an alternate function on each pin, configurable by <i>smartBASIC</i> . AIN configuration selected using GpioSetFunc() function.
SIO_04/AIN2/SPI_MISO – Analog Input	34	I	
SIO_03/AIN1 – Analog Input	49	I	Configurable 8, 10, 12-bit resolution.
SIO_02/AIN0 – Analog Input	50	I	Configurable voltage scaling 4, 2, 1/1, 1/3, 1/3, 1/4, 1/5, 1/6(default).
SIO_31/AIN7 – Analog Input	44	I	Configurable acquisition time 3uS, 5uS, 10uS(default), 15uS, 20uS, 40uS.
SIO_30/AIN6 – Analog Input	45	I	
SIO_29/AIN5 – Analog Input	48	I	Full scale input range (VDD)
SIO_28/AIN4 – Analog Input	46	I	

5.10.3 PWM Signal Output on up to 16 SIO Pins

The PWM output is an alternate function on ALL (GPIO) SIO pins, configurable by *smartBASIC* or the Nordic SDK.

The **PWM output** signal has a frequency and duty cycle property. Frequency is adjustable (up to 1 MHz) and the duty cycle can be set over a range from 0% to 100%.

PWM output signal has a frequency and duty cycle property. PWM output is generated using dedicated hardware in the chipset. There is a trade-off between PWM output frequency and resolution.

For example:

- PWM output frequency of 500 kHz (2 uS) results in resolution of 1:2.
- PWM output frequency of 100 kHz (10 uS) results in resolution of 1:10.
- PWM output frequency of 10 kHz (100 uS) results in resolution of 1:100.
- PWM output frequency of 1 kHz (1000 uS) results in resolution of 1:1000.

5.10.4 FREQ Signal Output on up to 16 SIO Pins

The FREQ output is an alternate function on 16 (GPIO) SIO pins, configurable by *smartBASIC* or Nordic SDK.

Note: The frequency driving each of the 16 SIO pins is the same but the duty cycle can be independently set for each pin.

FREQ output signal frequency can be set over a range of 0Hz to 4 MHz (with 50% mark-space ratio).

5.11 nRESET pin

Table 22: nRESET pin

Signal Name	Pin No	I/O	Comments
nRESET	19	I	BL654 HW reset (active low). Pull the nRESET pin low for minimum 100mS for the BL654 to reset.

5.12 Two-Wire Interface JTAG

The BL654 Firmware hex file consists of four elements:

- *smartBASIC* runtime engine
- Nordic Softdevice
- Master Bootloader

Laird Connectivity BL654 *smartBASIC* firmware (FW) image part numbers are referenced as w.x.y.z (ex. v29.x.y.z). The BL654 *smartBASIC* runtime engine and Softdevice combined image can be upgraded by the customer over the UART interface.

You also have the option to use the two-wire (JTAG) interface, during production, to clone the file system of a Golden preconfigured BL654 to others using the Flash Cloning process. This is described in the following application note *Flash Cloning for the BL654*. In this case the file system is also part of the .hex file.

Signal Name	Pin No	I/O	Comments
SWDIO	1	I/O	Internal pull-up resistor
SWDCLK	3	I	Internal pull-down resistor

The Laird Connectivity development board incorporates an on-board JTAG J-link programmer for this purpose. There is also the following JTAG connector which allows on-board JTAG J-link programmer signals to be routed off the development board. The only requirement is that you should use the following JTAG connector on the host PCB.

The JTAG connector MPN is as follows:

Reference	Part	Description and MPN (Manufacturers Part Number)
JP1	FTSH-105	Header, 1.27mm, SMD, 10-way, FTSH-105-01-L-DV Samtech

Note: Reference on the BL654 development board schematic (Figure 7) shows the DVK development schematic wiring only for the JTAG connector and the BL654 module JTAG pins.

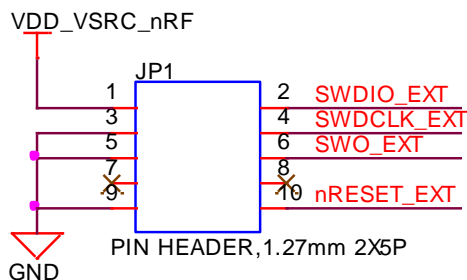


Figure 7: BL654 development board schematic

Note: The BL654 development board allows Laird Connectivity on-board JTAG J-link programmer signals to be routed off the development board by from connector JP1

JTAG is require because Nordic SDK applications can only be loaded using the JTAG (*smartBASIC* firmware can be loaded using JTAG as well as over the UART). We recommend that you use JTAG (2-wire SWD interface) to handle future BL654 module firmware upgrades. You **must** wire out the JTAG (2-wire SWD interface) on your host design (see [Figure 7](#), where the following four lines should be wired out – SWDIO, SWDCLK, GND and VCC). *smartBASIC* firmware upgrades can still be performed over the BL654 UART interface, but this is slower than using the BL654 JTAG (2-wire SWD interface) – (60 seconds using UART vs. 10 seconds when using JTAG).

SWO (SIO_32) is a Trace output (called SWO, Serial Wire Output) and is not necessary for programming BL654 over the SWD interface.

nRESET_BLE is not necessary for programming BL654 over the SWD interface.

Note: Nordic SDK is not supported on the BL654 USB dongle, part #451-00003.

5.13 BL654 Wakeup

5.13.1 Waking Up BL654 from Host

Wake the BL654 from the host using wake-up pins (any SIO pin). You may configure the BL654's wakeup pins via *smartBASIC* to do any of the following:

- Wake up when signal is low
- Wake up when signal is high
- Wake up when signal changes

Refer to the *smartBASIC* user guide for details. You can access this guide from the Laird Connectivity BL654 product page.

For BL654 wake-up using the Nordic SDK, refer to Nordic infocenter.nordicsemi.com.

5.14 Low Power Modes

The BL654 has three power modes: Run, Standby Doze, and Deep Sleep.

The module is placed automatically in Standby Doze if there are no pending events (when WAITEVENT statement is encountered within a customer's *smartBASIC* script). The module wakes from Standby Doze via any interrupt (such as a received character on the UART Rx line). If the module receives a UART character from either the external UART or the radio, it wakes up.

Deep sleep is the lowest power mode. Once awakened, the system goes through a system reset.

For different Nordic power modes using the Nordic SDK, refer to Nordic infocenter.nordicsemi.com.

5.15 Temperature Sensor

The on-silicon temperature sensor has a temperature range greater than or equal to the operating temperature of the device. Resolution is 0.25°C degrees. The on-silicon temperature sensor accuracy is $\pm 5^\circ\text{C}$.

To read temperature from on-silicon temperature sensor (in tenth of centigrade, so 23.4°C is output as 234) using *smartBASIC*:

- In command mode, use **ATI2024**
or
- From running a *smartBASIC* application script, use **SYSINFO(2024)**

5.16 Security/Privacy

5.16.1 Random Number Generator

Exposed via an API in *smartBASIC* (see *smartBASIC* documentation available from the BL654 product page). The **rand()** function from a running *smartBASIC* application returns a value.

For Nordic related functionality, visit Nordic infocenter.nordicsemi.com

5.16.2 AES Encryption/Decryption

Exposed via an API in *smartBASIC* (see *smartBASIC* documentation available from the BL654 product page). Function called **aesencrypt** and **aesdecrypt**.

For Nordic related functionality, visit Nordic infocenter.nordicsemi.com

5.16.3 ARM Cryptocell

ARM Cryptocell incorporates a true random generator (TRNG) and support for a wide range of asymmetric, symmetric and hashing cryptographic services for secure applications. For more information, please check the Nordic SDK.

5.16.4 Readback Protection

The BL654 supports readback protection capability that disallows the reading of the memory on the nrf52840 using a JTAG interface. Available via *smartBASIC* or the Nordic SDK.

5.16.5 Elliptic Curve Cryptography

The BL654 offers a range of functions for generating public/private keypair, calculating a shared secret, as well as generating an authenticated hash. Available via *smartBASIC* or the Nordic SDK.

5.17 Optional External 32.768 kHz crystal

This is not required for normal BL654 module operation.

The BL654 uses the on-chip 32.76 kHz RC oscillator (LFCLK) by default (which has an accuracy of ± 500 ppm) which requires regulator calibration (every eight seconds) to within ± 500 ppm.

You can connect an optional external high accuracy (± 20 ppm) 32.768 kHz crystal (and associated load capacitors) to the BL654SIO_01/XL2 (pin 41) and SIO_00/XL1 (pin 42) to provide improved protocol timing and to help with radio power consumption in the system standby doze/deep sleep modes by reducing the time that the RX window needs to be open. [Table 23](#) compares the current consumption difference between RC and crystal oscillator.

Table 23: Comparing current consumption difference between BL654 on-chip RC 32.76 kHz oscillator and optional external crystal (32.768kHz) based oscillator

	BL654 On-chip 32.768 kHz RC Oscillator (± 500 ppm) LFRC	Optional External Higher Accuracy (± 20 ppm) 32.768 kHz Crystal-based Oscillator LFXO
Current Consumption of 32.768 kHz Block	0.7 uA	0.23 uA
Standby Doze Current (SYSTEM ON IDLE +full RAM retention +RTC run current + LFRC or LFXO)	3.1 uA	2.6 uA
Calibration	Calibration required regularly (default eight seconds interval). Calibration takes 33 ms; with DCDC used, the total charge of a calibration event is 16 uC.	Not applicable

	BL654 On-chip 32.768 kHz RC Oscillator (±500 ppm) LFRC	Optional External Higher Accuracy (±20 ppm) 32.768 kHz Crystal-based Oscillator LFXO
	<p>The average current consumed by the calibration depends on the calibration interval and can be calculated using the following formula:</p> <p>CAL_charge/CAL_interval – The lowest calibration interval (0.25 seconds) provides an average current of (DCDC enabled): 16uC/0.25s = 64uA</p> <p>To get the 500-ppm accuracy, the BLE stack specification states that a calibration interval of eight seconds is enough. This gives an average current of: 16uC/8s = 2 uA</p> <p>Added to the LFRC run current and Standby Doze (IDLE) base current shown above results in a total average current of: LFRC + CAL = 3.1 + 2 = 5.1 uA</p>	
Total	5.1 uA	2.6 uA
Summary	<ul style="list-style-type: none"> Low current consumption Accuracy 500 ppm 	<ul style="list-style-type: none"> Lowest current consumption Needs external crystal High accuracy (depends on the crystal, usually 20 ppm)

Table 24: Optional external 32.768 kHz crystal specification

Optional external 32.768kHz crystal	Min	Typ	Max
Crystal Frequency	-	32.768 kHz	-
Frequency tolerance requirement of BLE stack	-	-	±500 ppm
Load Capacitance	-	-	12.5 pF
Shunt Capacitance	-	-	2 pF
Equivalent series resistance	-	-	100 kOhm
Drive level	-	-	1 uW
Input capacitance on XL1 and XL2 pads	-	4 pF	-
Run current for 32.768 kHz crystal based oscillator	-	0.23 uA	-
Start-up time for 32.768 kHz crystal based oscillator	-	0.25 seconds	-
Peak to peak amplitude for external low swing clock input signal must not be outside supply rails	200 mV	-	1000 mV

Be sure to tune the load capacitors on the board design to optimize frequency accuracy (at room temperature) so it matches that of the same crystal standalone, Drive Level (so crystal operated within safe limits) and oscillation margin (R_{neg} is at least 3 to 5 times ESR) over the operating temperature range.

5.18 451-00001 On-board PCB Antenna Characteristics

The 451-00001 on-board PCB trace monopole antenna radiated performance depends on the host PCB layout.

The BL654 development board was used for BL654 development and the 451-00001 PCB antenna performance evaluation. To obtain similar performance, follow guidelines in section *PCB Layout on Host PCB for the 451-00001* to allow the on-board PCB antenna to radiate and reduce proximity effects due to nearby host PCB GND copper or metal covers.

	f(MHz)	Antenna P (dBm)	TRP (dBm)	Max EIRP (dBm)	Efficiency (dB)	Gain (dBi)
BL654	2402	0.00	-4.75	-1.19	-4.8	-1.2
	2440	0.00	-3.55	0.18	-3.6	0.2
	2480	0.00	-2.82	0.71	-2.8	0.7

- Notes:**
- Antenna P = Antenna input power (set).
 - TRP = Total Radiated Power (measured).
 - EIRP = Equivalent Isotropic (ideal) Radiated Power (measured).
 - Efficiency = TRP - Antenna P (calculated).
 - Gain = Max. EIRP - Antenna P (calculated).

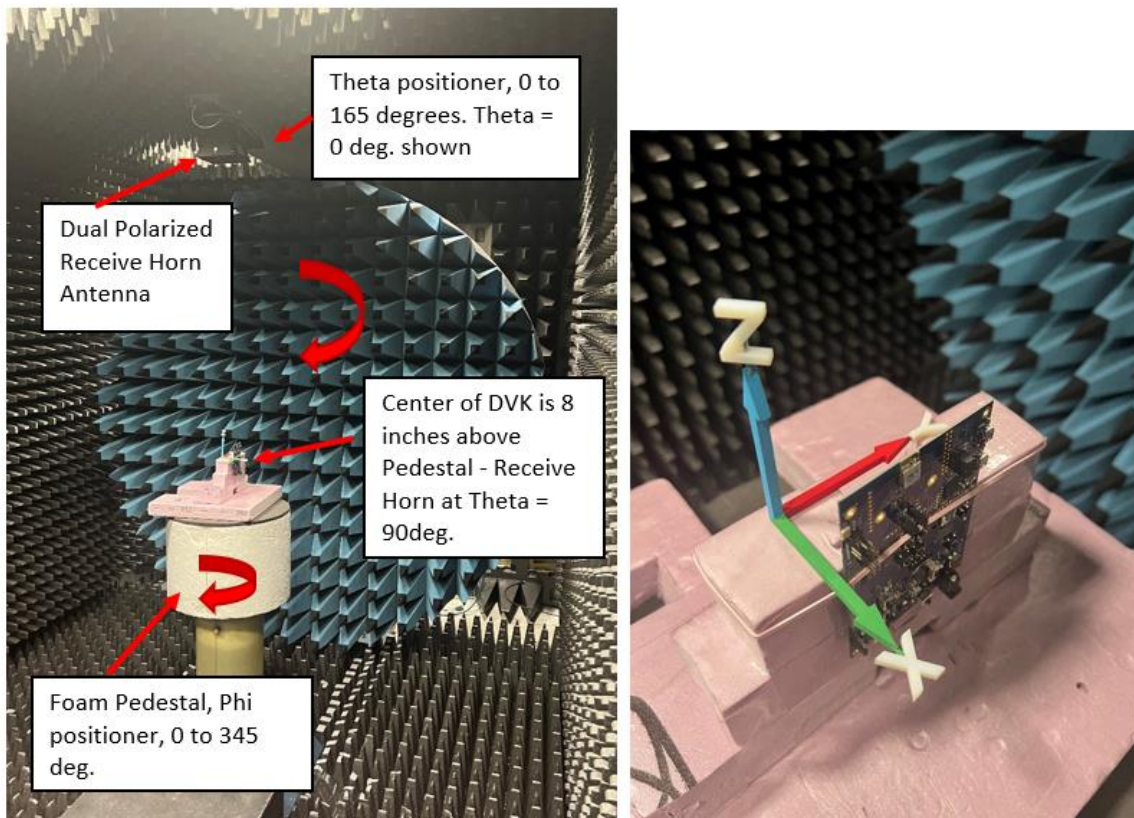
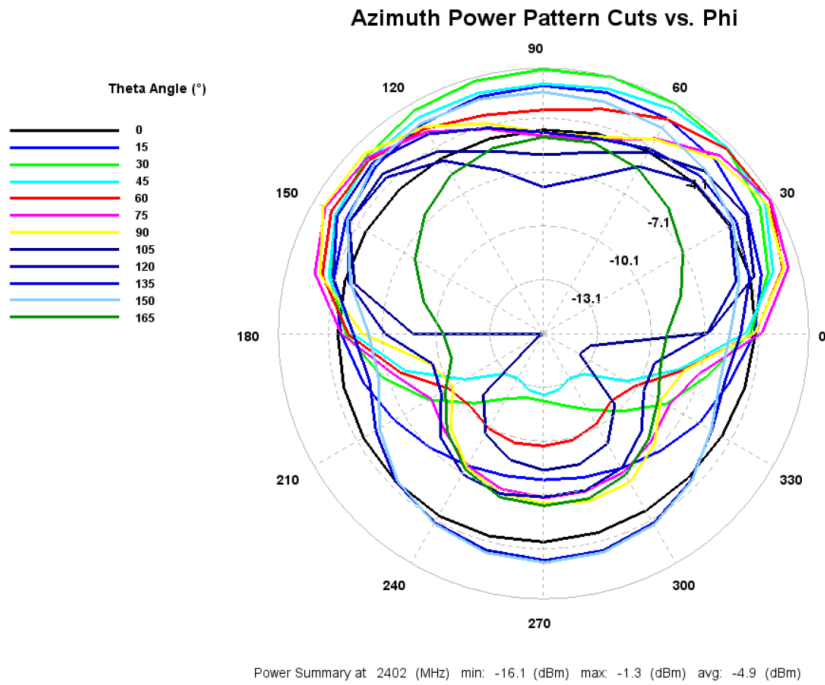


Figure 8: Radiated Performance Measurement Setup

5.18.1 2402MHz Radiated Performance

EIRP Azimuth Cut



3D Plots:

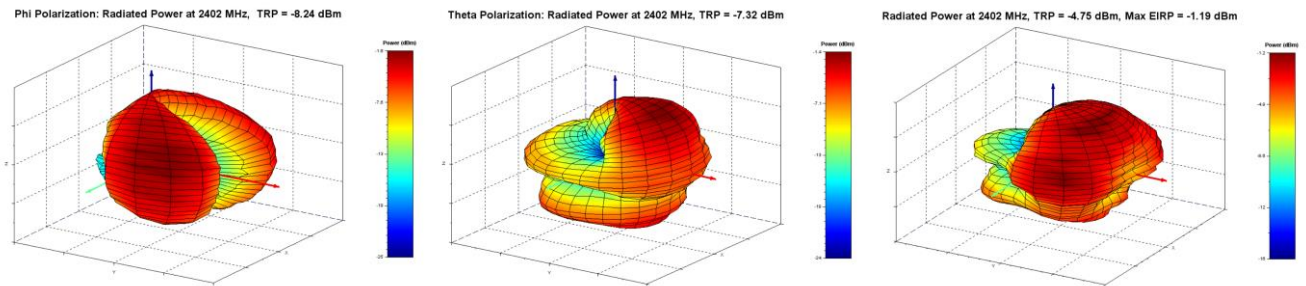
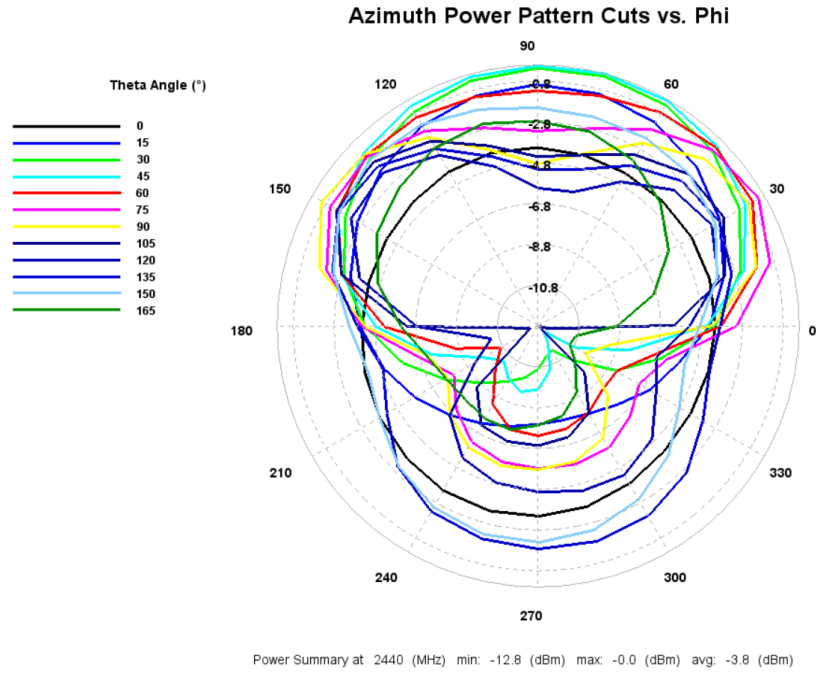


Figure 9: 2402MHz Horizontal, Vertical, and Total Patterns

5.18.2 2440MHz Radiated Performance

EIRP Azimuth Cut



3D Plots:

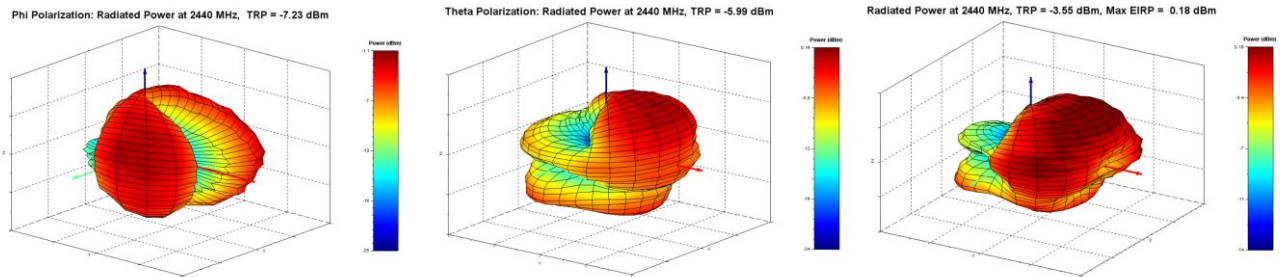
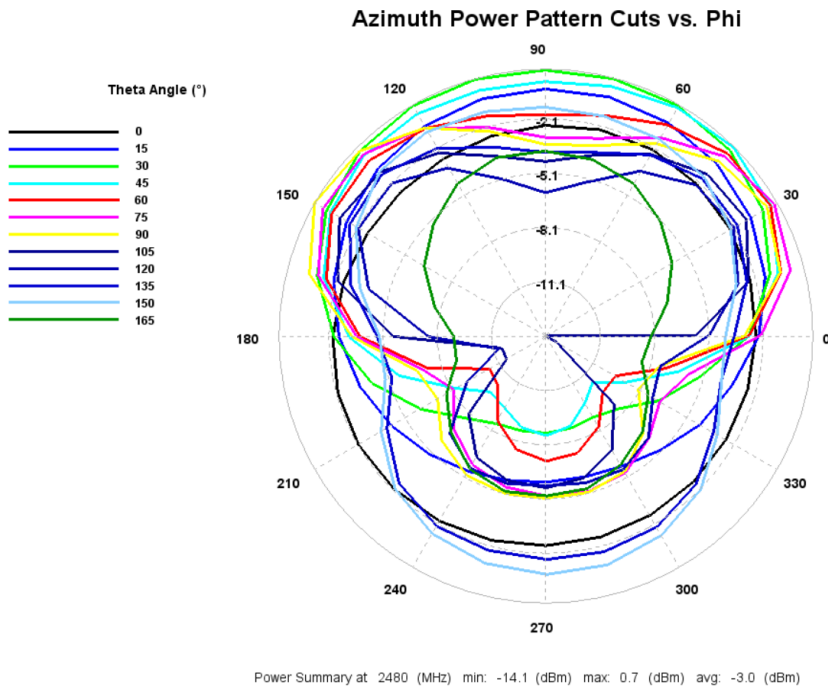


Figure 10: 2440MHz Horizontal, Vertical, and Total Patterns

5.18.3 2480MHz Radiated Performance

EIRP Azimuth Cut



3D Plots:

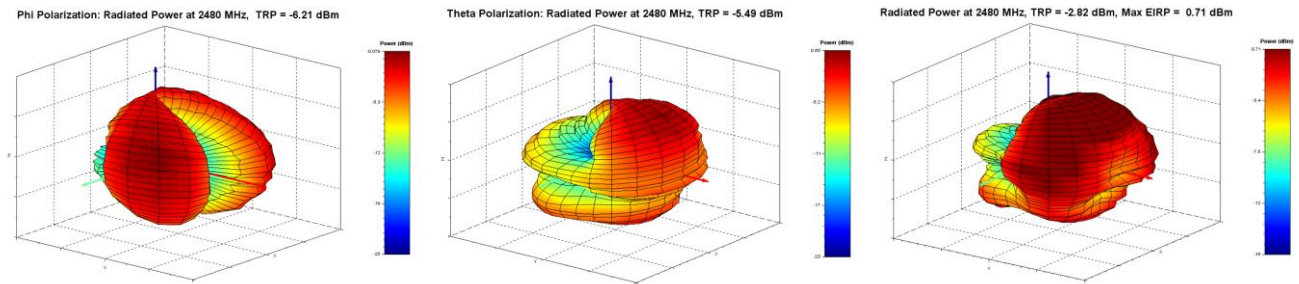


Figure 11: 2480MHz Horizontal, Vertical, and Total Patterns

5.18.4451-00001 Return Loss Measurement

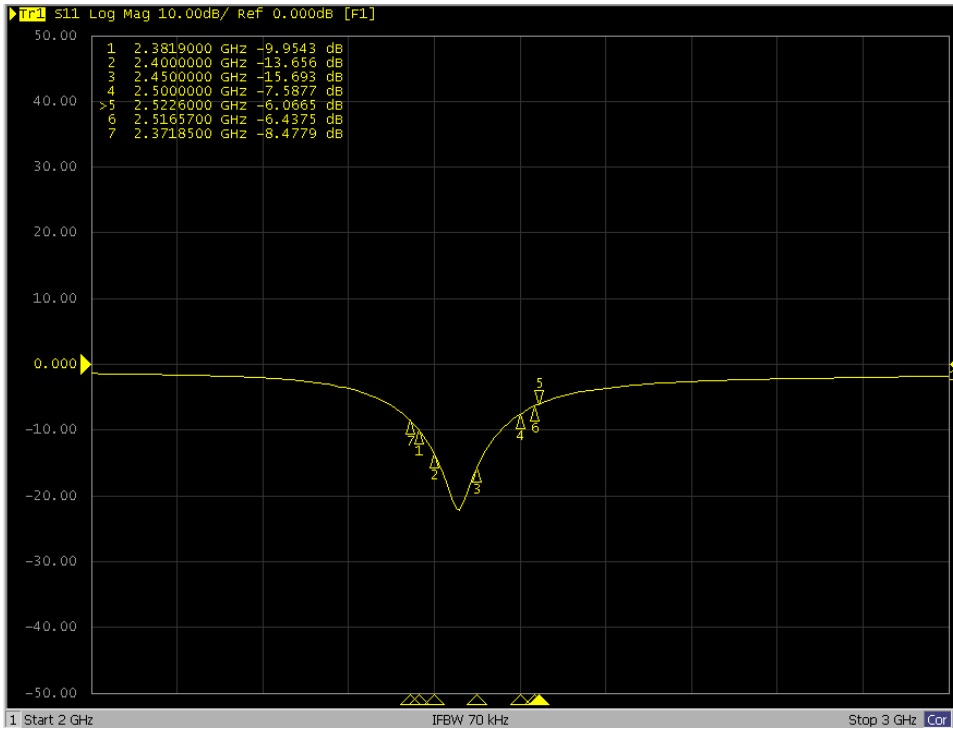


Figure 12: 451-00001 on-board PCB antenna performance (Antenna Gain and S11 – whilst 451-00001 module sitting on Devboard 455-00001)

5.19 451-00003 USB BLE 5.1 Dongle Mechanical Details

Note: The BL654-US Dongle User Guide is available in the Documentation section of the Laird Connectivity BL654 product page – <https://www.lairdconnect.com/wireless-modules/bluetooth-modules/bluetooth-5-modules/bl654-series-bluetooth-module-nfc>

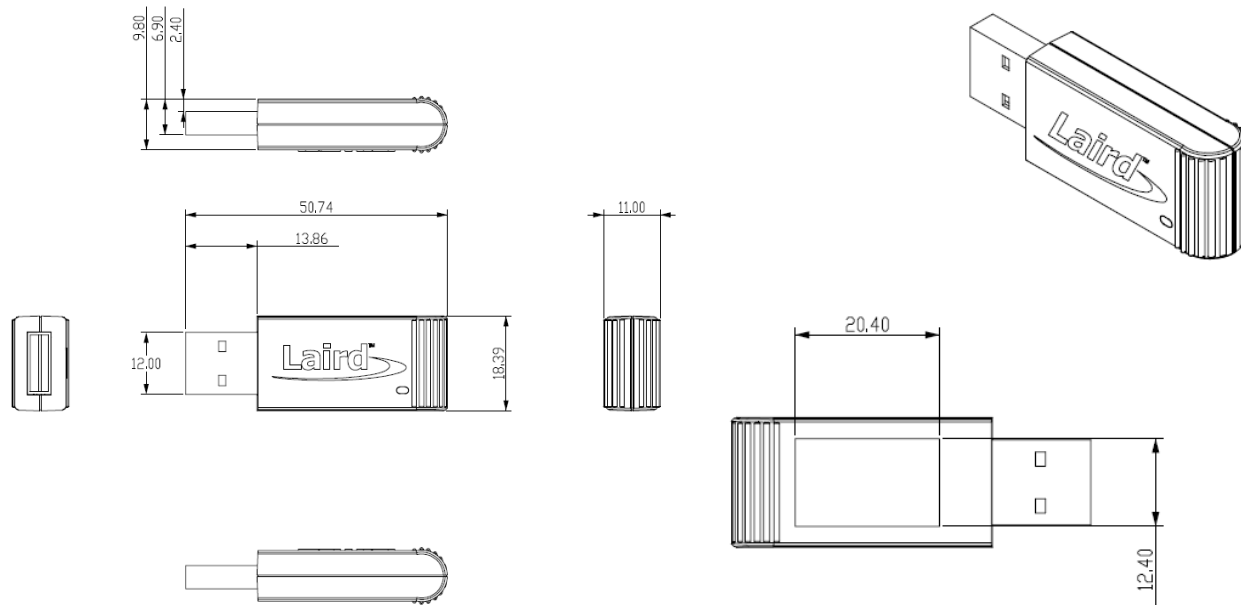


Figure 13: 451-00003 USB BLE 5.1 Dongle Mechanical details

6 HARDWARE INTEGRATION SUGGESTIONS

6.1 Circuit

The BL654 is easy to integrate, requiring no external components on your board apart from those which you require for development and in your end application.

The following are suggestions for your design for the best performance and functionality.

Checklist (for Schematic):

- **BL654 power supply options:**

Option 1 – Normal voltage power supply mode entered when the external supply voltage is connected to both the VDD and VDDH pins (so that VDD equals VDD_HV). Connect external supply within range 1.7V to 3.6V range to BL654 VDD and VDD_HV pins.

OR

Option 2 – High voltage mode power supply mode (using BL654 VDD_HV pin) entered when the external supply voltage is ONLY connected to the VDDH pin and the VDD pin is not connected to any external voltage supply. Connect external supply within range 2.5V to 5.5V range to BL654 VDD_HV pin. BL654 VDD pin left unconnected.

Nordic Errata 197 and 202 related to the use of VDD_HV DCDC convertor, for details refer to http://infocenter.nordicsemi.com/pdf/nRF52840_Rev_1_Errata_v1.1.pdf. Nordic Errata 202 means no external current draw (from VDD pin) is allowed during power up and VDD_HV rise time (to 3V) is below 1mS.

For either option, if you use USB interface then the BL654 VBUS pin must be connected to external supply within the range 4.35V to 5.5V. When using the BL654 VBUS pin, you MUST externally fit a 4.7uF to ground.

External power source should be within the operating range, rise time and noise/ripple specification of the BL654. Add decoupling capacitors for filtering the external source. Power-on reset circuitry within BL654 series module incorporates brown-out detector, thus simplifying your power supply design. Upon application of power, the internal power-on reset ensures that the module starts correctly.

- **VDD and coin-cell operation**

With a built-in DCDC (operating range 1.7V to 3.6V), that reduces the peak current required from a coin-cell, making it easier to use with a coin-cell.

- **AIN (ADC) and SIO pin IO voltage levels**

BL654 SIO voltage levels are at VDD. Ensure input voltage levels into SIO pins are at VDD also (if VDD source is a battery whose voltage will drop). Ensure ADC pin maximum input voltage for damage is not violated.

- **AIN (ADC) impedance and external voltage divider setup**

If you need to measure with ADC a voltage higher than 3.6V, you can connect a high impedance voltage divider to lower the voltage to the ADC input pin.

- **JTAG**

This is REQUIRED as Nordic SDK applications can only be loaded using the JTAG (*smartBASIC* firmware can be loaded using the JTAG as well as the UART).

Laird Connectivity recommends you use JTAG (2-wire interface) to handle future BL654 module firmware upgrades. You MUST wire out the JTAG (2-wire interface) on your host design (see Figure 7, where four lines should be wired out, namely SWDIO, SWDCLK, GND and VCC). Firmware upgrades can still be performed over the BL654 UART interface, but this is slower (60 seconds using UART vs. 10 seconds when using JTAG) than using the BL654 JTAG (2-wire interface). JTAG may be used if you intend to use Flash Cloning during production to load *smartBASIC* scripts.

- **UART**

Required for loading your *smartBASIC* application script during development (or for subsequent firmware upgrades (except JTAG for FW upgrades and/or Flash Cloning of the *smartBASIC* application script). Add connector to allow interfacing with UART via PC (UART-RS232 or UART-USB).

- **UART_RX and UART_CTS**

SIO_08 (alternative function UART_RX) is an input, set with internal weak pull-up (in firmware). The pull-up prevents the module from going into deep sleep when UART_RX line is idling.

SIO_07 (alternative function UART_CTS) is an input, set with internal weak pull-down (in firmware). This pull-down ensures the default state of the UART_CTS will be asserted which means can send data out of the UART_TX line. Laird Connectivity recommends that UART_CTS be connected.

- **nAutoRUN pin and operating mode selection**

nAutoRUN pin needs to be externally held high or low to select between the two BL654 operating modes at power-up:

- Self-contained Run mode (nAutoRUN pin held at 0V).
- Interactive / development mode (nAutoRUN pin held at VDD).

Make provision to allow operation in the required mode. Add jumper to allow nAutoRUN pin to be held high or low (BL654 has internal 13K pull-down by default) OR driven by host GPIO.

- **I2C**

It is essential to remember that pull-up resistors on both I2C_SCL and I2C_SDA lines are not provided in the BL654 module and MUST be provided external to the module as per I2C standard.

- **SPI**

Implement SPI chip select using any unused SIO pin within your *smartBASIC* application script or Nordic application then SPI_CS is controlled from the software application allowing multi-dropping.

- **SIO pin direction**

BL654 modules shipped from production with *smartBASIC* FW, all SIO pins (with default function of DIO) are mostly digital inputs (see Pin Definitions Table2). Remember to change the direction SIO pin (in your *smartBASIC* application script) if that particular pin is wired to a device that expects to be driven by the BL654 SIO pin configured as an output. Also, these SIO pins have the internal pull-up or pull-down resistor-enabled by default in firmware (see Pin Definitions Table 2). This was done to avoid floating inputs, which can cause current consumption in low power modes (e.g. StandbyDoze) to drift with time. You can disable the PULL-UP or Pull-down through their *smartBASIC* application.

Note: Internal pull-up, pull down will take current from VDD.

- **SIO_02 pin and OTA *smartBASIC* application download feature**

SIO_02 is an input, set with internal pull-down (in FW). Refer to latest firmware release documentation on how SIO_02 is used for Over the Air *smartBASIC* application download feature. The SIO_02 pin must be pulled high externally to enable

the feature. Decide if this feature is required in production. When SIO_02 is high, ensure nAutoRun is NOT high at same time; otherwise you cannot load the *smartBASIC* application script.

- **NFC antenna connector**

To make use of the Laird Connectivity flexi-PCB NFC antenna, fit connector:

- Description – FFC/FPC Connector, Right Angle, SMD/90d, Dual Contact, 1.2 mm Mated Height
- Manufacturer – Molex
- Manufacturers Part number – 512810594

Add tuning capacitors of 300 pF on NFC1 pin to GND and 300 pF on NFC2 pins to GND if the PCB track length is similar as development board.

- **nRESET pin (active low)**

Hardware reset. Wire out to push button or drive by host.

By default module is out of reset when power applied to VCC pins.

- **Optional External 32.768kHz crystal**

If the optional external 32.768kHz crystal is needed then use a crystal that meets specification and add load capacitors whose values should be tuned to meet all specification for frequency and oscillation margin.

- **SIO_38 special function pin**

This is for future use by Laird Connectivity. It is currently a Do Not Connect pin if using the *smartBASIC* FW.

6.2 PCB Layout on Host PCB - General

Checklist (for PCB):

- MUST locate BL654 module close to the edge of PCB (mandatory for the 451-00001 for on-board PCB trace antenna to radiate properly).
- Use solid GND plane on inner layer (for best EMC and RF performance).
- All module GND pins MUST be connected to host PCB GND.
- Place GND vias close to module GND pads as possible.
- Unused PCB area on surface layer can be flooded with copper but place GND vias regularly to connect the copper flood to the inner GND plane. If GND flood copper is on the bottom of the module, then connect it with GND vias to the inner GND plane.
- Route traces to avoid noise being picked up on VDD, VDDH, VBUS supply and AIN (analogue) and SIO (digital) traces.
- Ensure no exposed copper is on the underside of the module (refer to land pattern of BL654 development board).

6.3 PCB Layout on Host PCB for the 451-00001

6.3.1 Antenna Keep-out on Host PCB

The 451-00001 has an integrated PCB trace antenna and its performance is sensitive to host PCB. It is critical to locate the 451-00001 on the edge of the host PCB (or corner) to allow the antenna to radiate properly. Refer to guidelines in section **PCB land pattern and antenna keep-out area for the 451-00001**. Some of those guidelines are repeated below.

- Ensure there is no copper in the antenna keep-out area on any layers of the host PCB. Keep all mounting hardware and metal clear of the area to allow proper antenna radiation.
- For best antenna performance, place the 451-00001 module on the edge of the host PCB, preferably in the edge center.
- The BL654 development board has the 451-00001 module on the edge of the board (not in the corner). The antenna keep-out area is defined by the BL654 development board which was used for module development and antenna performance evaluation is shown in [Figure 14](#), where the antenna keep-out area is ~5 mm wide, ~39.95 mm long; with PCB dielectric (no copper) height ~1 mm sitting under the 451-00001 PCB trace antenna.
- The 451-00001 PCB trace antenna is tuned when the 451-00001 is sitting on development board (host PCB) with size of 125 mm x 85 mm x 1mm.
- A different host PCB thickness dielectric will have small effect on antenna.
- The antenna-keep-out defined in the [Host PCB Land Pattern and Antenna Keep-out for the 451-00001](#) section.

- Host PCB land pattern and antenna keep-out for the BL654 applies when the 451-00001 is placed in the edge of the host PCB preferably in the edge center. Figure 14 shows an example.

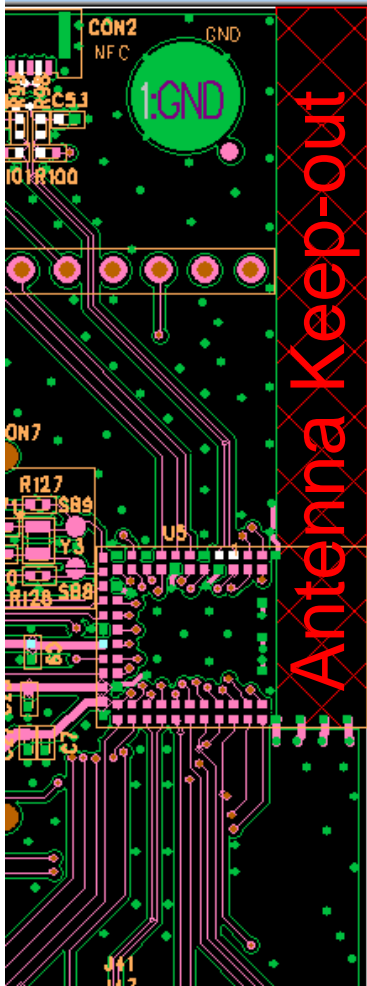


Figure 14: PCB trace Antenna keep-out area (shown in red), corner of the BL654 development board for the 451-00001 module.

Antenna Keep-out Notes:

- | | |
|---------------|----------------------------------------------------------------------------------------------------|
| Note 1 | The BL654 module is placed on the edge, preferably edge centre of the host PCB. |
| Note 2 | Copper cut-away on all layers in the <i>Antenna Keep-out</i> area under the 451-00001 on host PCB. |

6.3.2 Antenna Keep-out and Proximity to Metal or Plastic

Checklist (for metal /plastic enclosure):

- Minimum safe distance for metals without seriously compromising the antenna (tuning) is 40 mm top/bottom and 30 mm left or right.
- Metal close to the 451-00001 PCB trace monopole antenna (bottom, top, left, right, any direction) will have degradation on the antenna performance. The amount of that degradation is entirely system dependent, meaning you will need to perform some testing with your host application.
- Any metal closer than 20 mm will begin to significantly degrade performance (S11, gain, radiation efficiency).
- It is best that you test the range with a mock-up (or actual prototype) of the product to assess effects of enclosure height (and materials, whether metal or plastic).

6.4 External Antenna Integration with the 451-00002

Please refer to the regulatory sections for FCC, ISSED, EU, and Japan for details of use of BL654-with external antennas in each regulatory region.

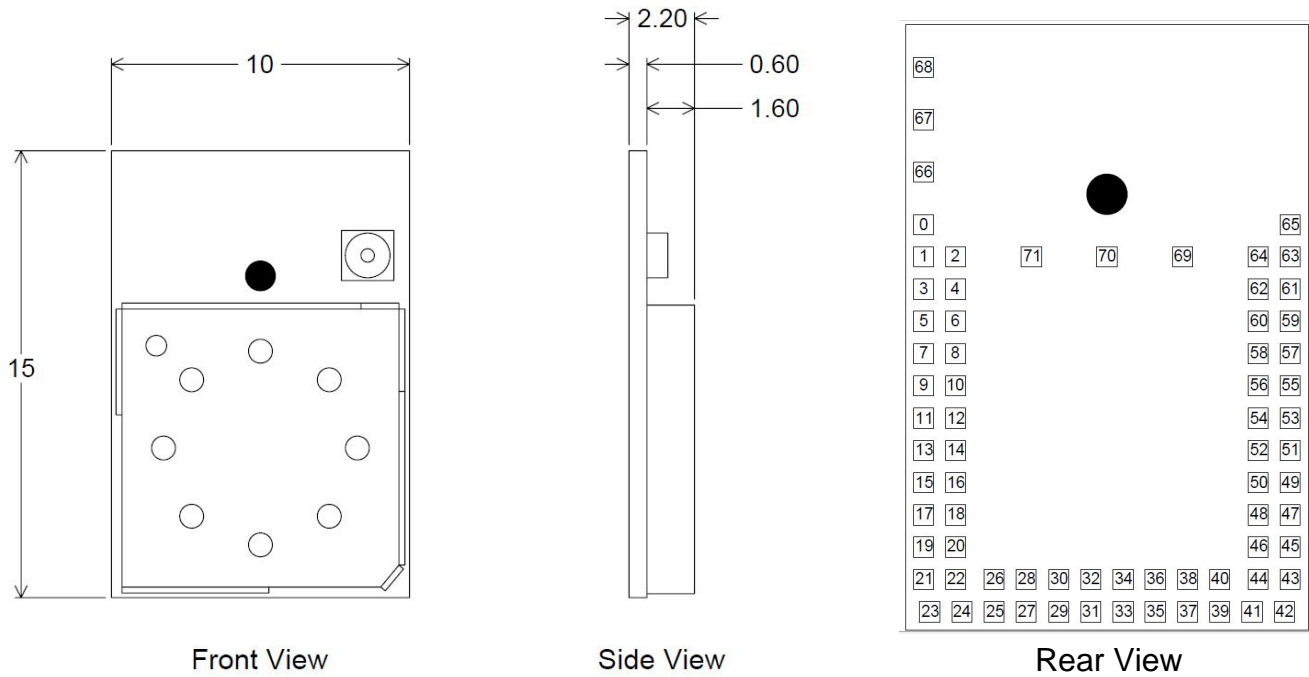
The BL654 family has been designed to operate with the below external antennas (with a maximum gain of 2.0 dBi). The required antenna impedance is 50 ohms. See [Table 25](#). External antennas improve radiation efficiency.

Table 25: External antennas for the BL654

Manufacturer	Model	Laird Connectivity Part Number	Type	Connector	Peak Gain	
					2400-2500 MHz	2400-2480 MHz
Laird Connectivity	NanoBlue	EBL2400A1-10MH4L	PCB Dipole	IPEX MHF4	2 dBi	-
Laird Connectivity	FlexPIFA	001-0022	Patch	IPEX MHF4	-	2 dBi
Laird Connectivity	FlexNotch	001-0023	Notch	IPEX MHF4	-	2 dBi
Mag.Layers	EDA-8709-2G4C1-B27-CY	0600-00057	Dipole	IPEX MHF4	2 dBi	-
Laird Connectivity	mFlexPIFA	EFA2400A3S-10MH4L	PIFA	IPEX MHF4	-	2 dBi
Laird Connectivity	Laird Connectivity NFC	0600-00061	NFC	N/A	-	-
Walsin	RFDPA870900SBAB8G1	NA	Dipole	SMA	2dBi	

7 MECHANICAL DETAILS

7.1 BL654 Mechanical Details



Tolerances

Board Outline: +/- 0.13mm
Board Height: +/- 0.15mm

Figure 15: BL654 mechanical drawing

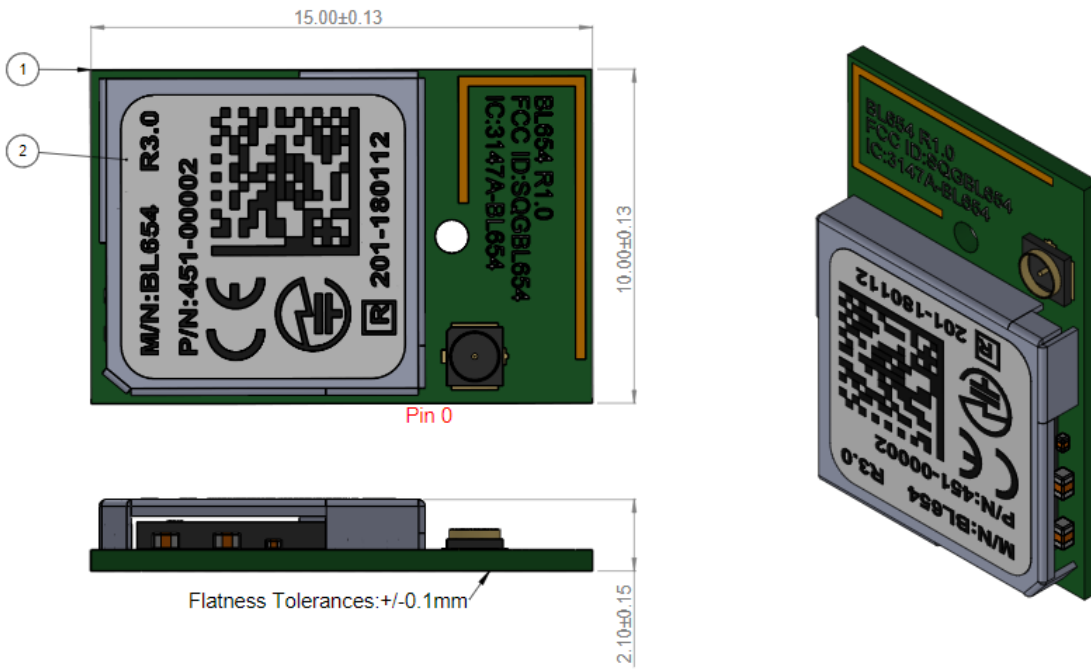


Figure 16: Mechanical Details - External Antenna

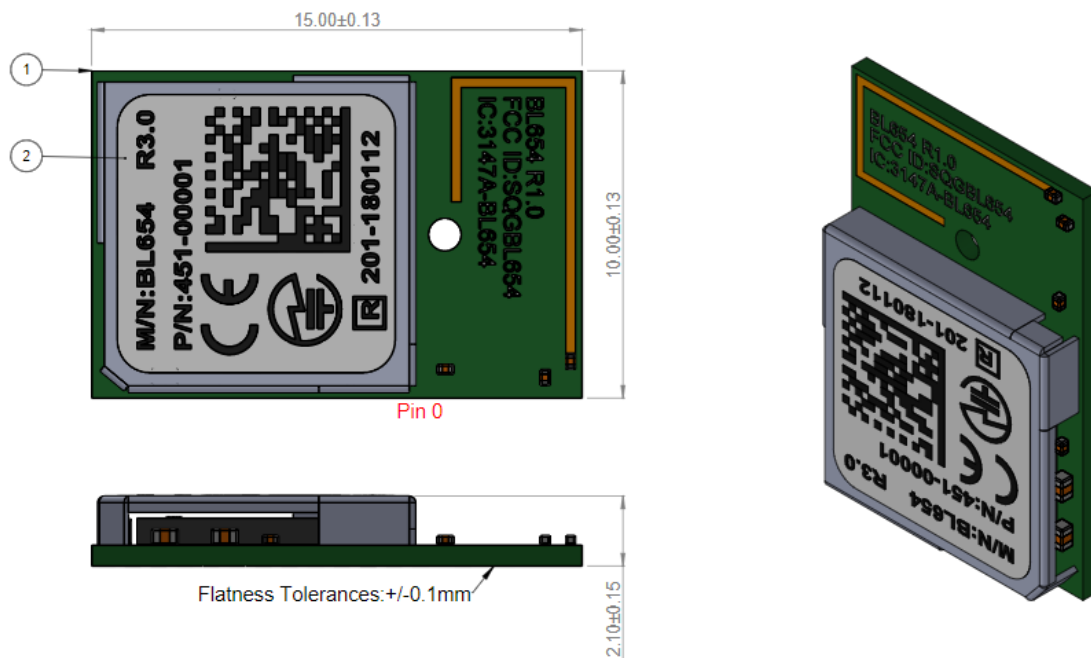


Figure 17: Mechanical Antennas - Integrated Antenna

Development Kit Schematics can be found in the software downloads tab of the BL654 product page – <https://www.lairdconnect.com/wireless-modules/bluetooth-modules/bluetooth-5-modules/bl654-series-bluetooth-module-nfc>

7.2 Host PCB Land Pattern and Antenna Keep-out for the 451-00001

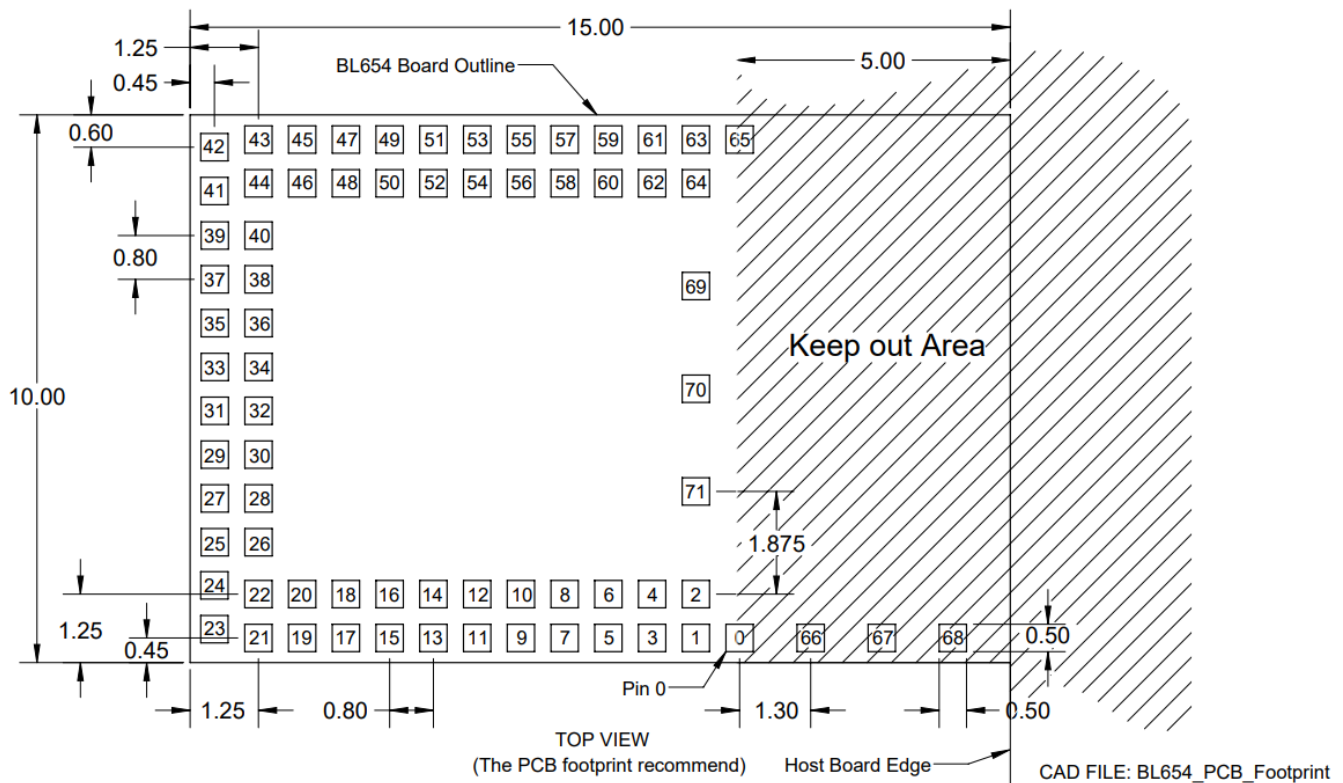


Figure 18: Land pattern and Keep-out for the 451-00001

All dimensions are in mm.

Host PCB Land Pattern and Antenna Keep-out for the 451-00001 Notes:

Note 1	Ensure there is no copper in the antenna 'keep out area' on any layers of the host PCB. Also keep all mounting hardware or any metal clear of the area (Refer to 6.3.2) to reduce effects of proximity detuning the antenna and to help antenna radiate properly.
Note 2	For the best on-board antenna performance, the module 451-00001 MUST be placed on the edge of the host PCB and preferably in the edge centre and host PCB, the antenna "Keep Out Area" is extended (see Note 4).
Note 3	BL654 development board has the 451-00001 placed on the edge of the PCB board (and not in corner) for that the Antenna keep out area is extended down to the corner of the development board, see section PCB Layout on Host PCB for the 451-00001 , Figure 18. This was used for module development and antenna performance evaluation.
Note 4	Ensure that there is no exposed copper under the module on the host PCB.
Note 5	You may modify the PCB land pattern dimensions based on their experience and/or process capability.

8 APPLICATION NOTE FOR SURFACE MOUNT MODULES

8.1 Introduction

Laird Connectivity surface mount modules are designed to conform to all major manufacturing guidelines. This application note is intended to provide additional guidance beyond the information that is presented in the User Manual. This Application Note is considered a living document and will be updated as new information is presented.

The modules are designed to meet the needs of several commercial and industrial applications. They are easy to manufacture and conform to current automated manufacturing processes.

8.2 Shipping

8.2.1 Tape and Reel Package Information

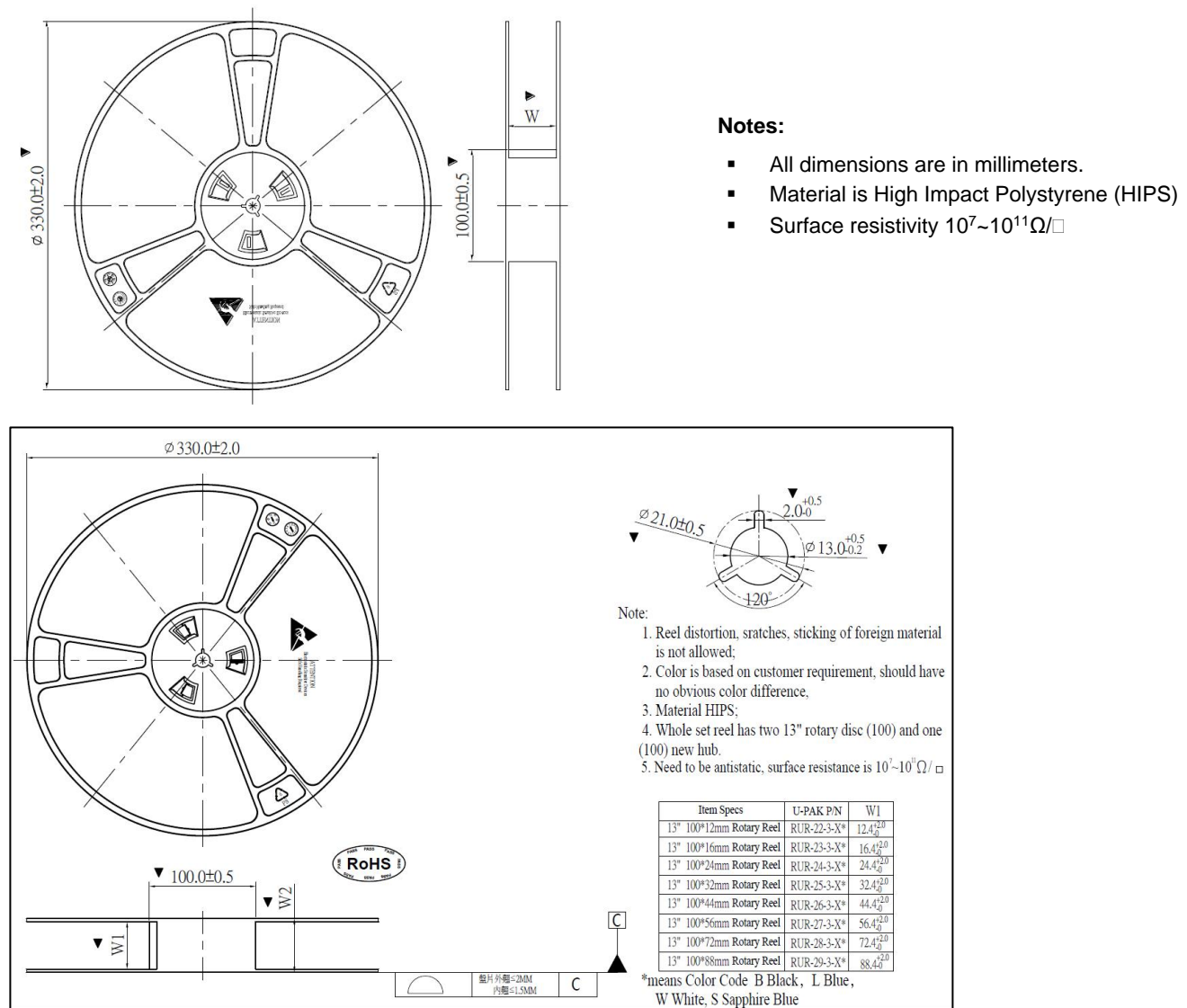
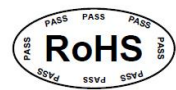
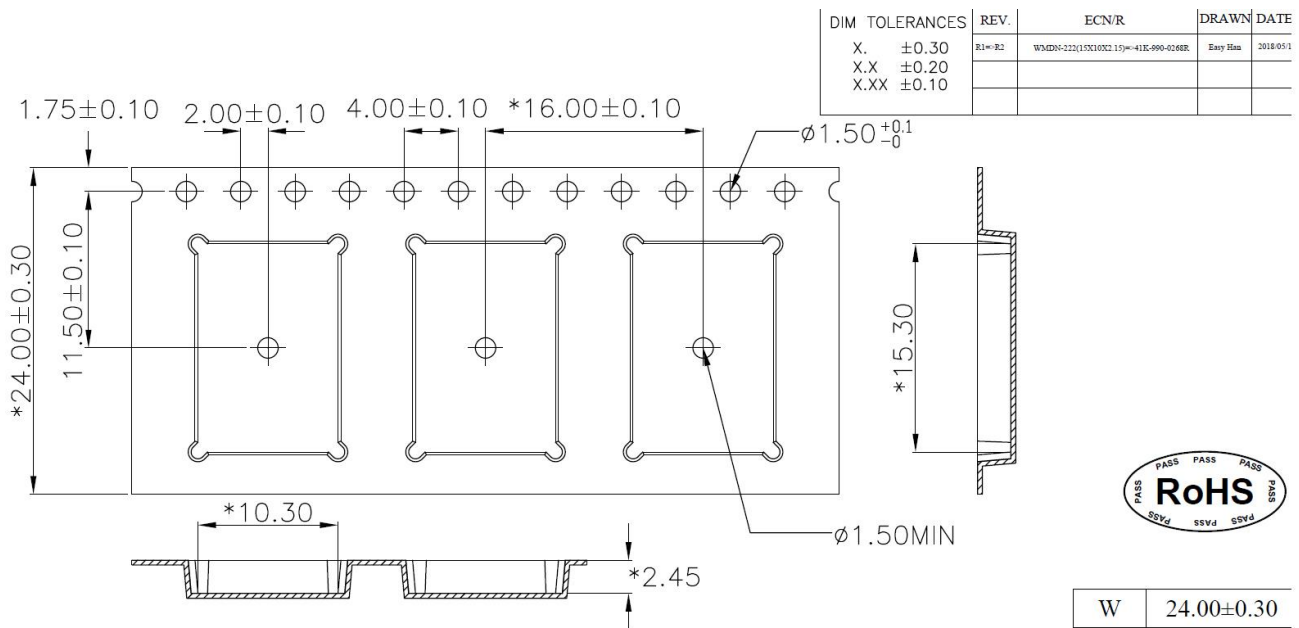


Figure 19: Reel specifications



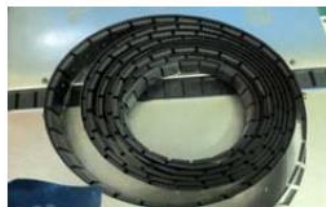
1. 10 sprocket hole pitch cumulative tolerance ± 0.20 .
2. Carrier camber is within 1 mm in 250 mm.
3. Material : Black Conductive Polystyrene Alloy.
4. All dimensions meet EIA-481-D requirements.
5. Thickness : 0.35 ± 0.05 mm.
6. Packing length per 13" reel : 18.0 Meters.(RUR-24-3-TL)
7. Component load per 13" reel : 1000 pcs.(前后留空各35PCS)

Figure 20: Tape specifications (Module Orientation – Module Antenna Side away from Tape holes)

There are 1,000 x BL654 modules taped in a reel (and packaged in a pizza box) and five boxes per carton (5000 modules per carton). Reel, boxes, and carton are labeled with the appropriate labels. See [Carton Contents](#) for more information.

8.2.2 Carton Contents

The following are the contents of the carton shipped for the BL654 modules.



PCBA: 5000 pcs/ctn



Reel: 5 pcs/ctn



Bag: 5 pcs/ctn

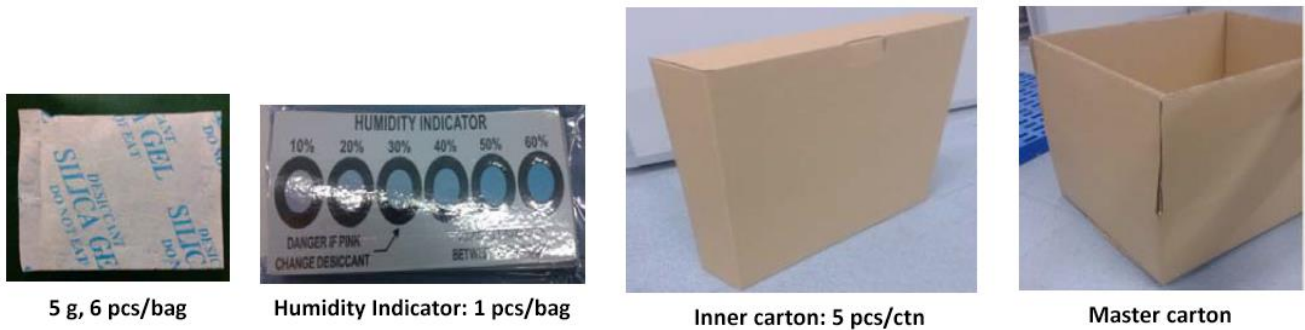


Figure 21: Carton contents for the BL654

8.2.3 Packaging Process

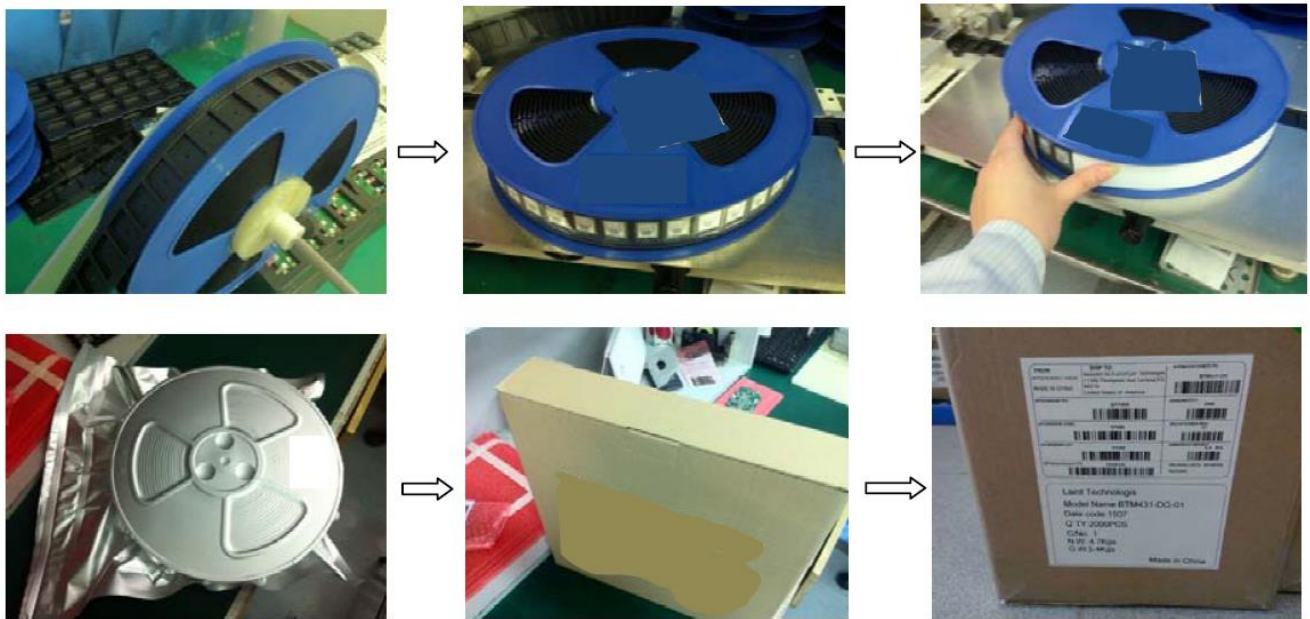


Figure 22: BL654 packaging process

8.2.4 Labeling

The following labels are located on the antistatic bag:



Figure 23: Antistatic bag labels

The following package label is located on both sides of the master carton:

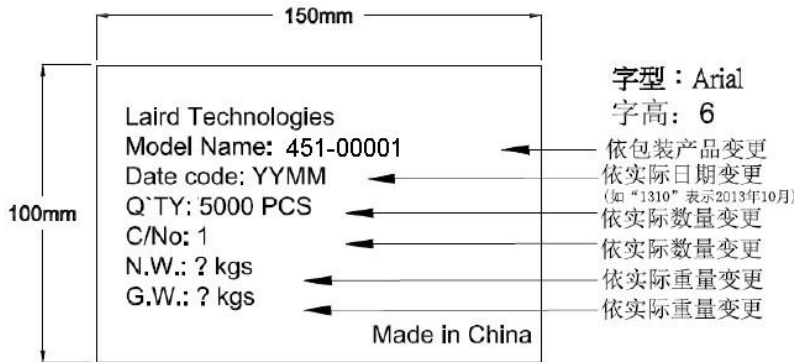


Figure 24: Master carton package label

The following is the packing slip label:

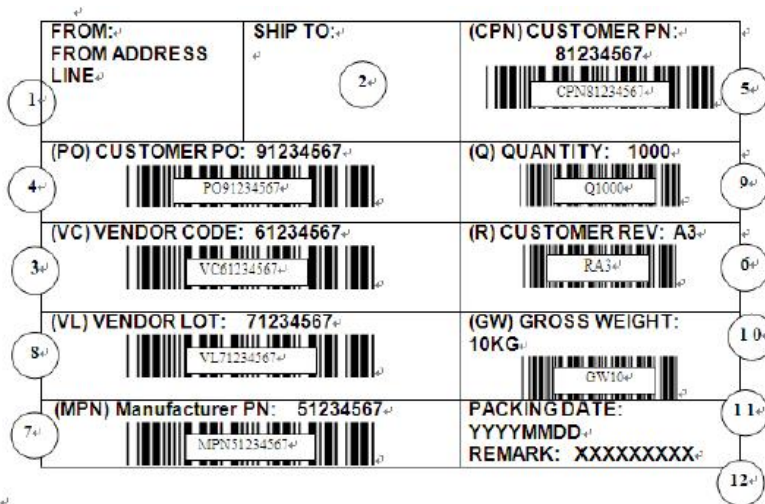


Figure 25: Packing slip label

8.3 Reflow Parameters

Prior to any reflow, it is important to ensure the modules were packaged to prevent moisture absorption. New packages contain desiccant (to absorb moisture) and a humidity indicator card to display the level maintained during storage and shipment. If directed to *bake units* on the card, see Table 26 and follow instructions specified by IPC/JEDEC J-STD-033. A copy of this standard is available from the JEDEC website: <http://www.jedec.org/sites/default/files/docs/jstd033b01.pdf>

Any modules not manufactured before exceeding their floor life should be re-packaged with fresh desiccant and a new humidity indicator card. Floor life for MSL (Moisture Sensitivity Level) four devices is 72 hours in ambient environment $\leq 30^{\circ}\text{C}/60\%\text{RH}$.

Table 26: Recommended baking times and temperatures

MSL	125°C Baking Temp.		90°C/≤5%RH Baking Temp.		40°C/≤5%RH Baking Temp.	
	Saturated @ 30°C/85%	Floor Life Limit + 72 hours @ 30°C/60%	Saturated @ 30°C/85%	Floor Life Limit + 72 hours @ 30°C/60%	Saturated @ 30°C/85%	Floor Life Limit + 72 hours @ 30°C/60%
4	11 hours	7 hours	37 hours	23 hours	15 days	9 days

Laird Connectivity surface mount modules are designed to be easily manufactured, including reflow soldering to a PCB. Ultimately it is the responsibility of the customer to choose the appropriate solder paste and to ensure oven temperatures during reflow meet the requirements of the solder paste. Laird Connectivity surface mount modules conform to J-STD-020D1 standards for reflow temperatures.

Important: During reflow, modules should not be above 260° and not for more than 30 seconds. In addition, we recommend that the BL654 module **does not** go through the reflow process more than one time; otherwise the BL654 internal component soldering may be impacted.

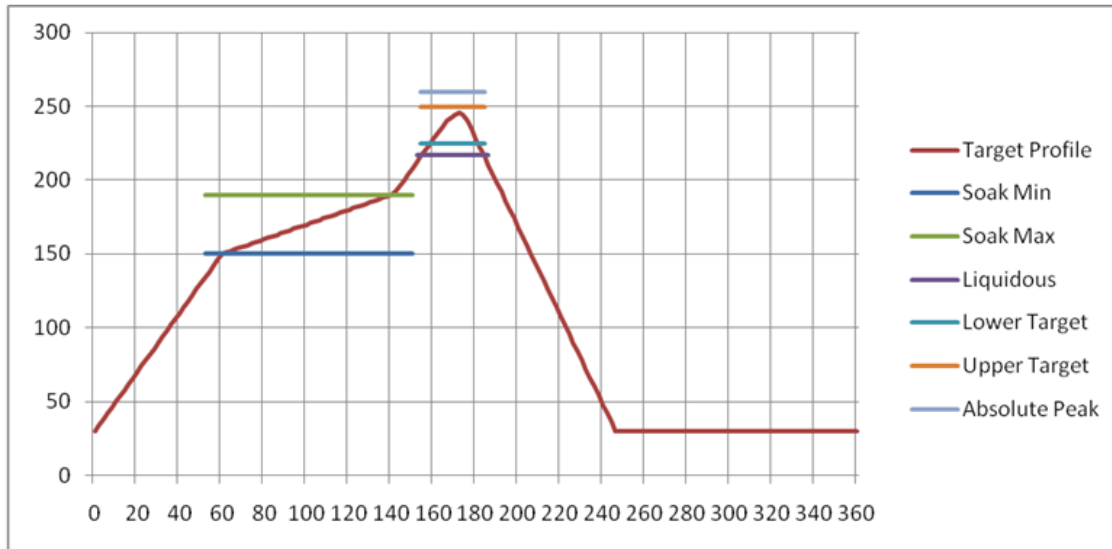


Figure 26: Recommended reflow temperature

Temperatures should not exceed the minimums or maximums presented in [Table 27](#).

Table 27: Recommended maximum and minimum temperatures

Specification	Value	Unit
Temperature Inc./Dec. Rate (max)	1~3	°C / Sec
Temperature Decrease rate (goal)	2-4	°C / Sec
Soak Temp Increase rate (goal)	.5 - 1	°C / Sec
Flux Soak Period (Min)	70	Sec
Flux Soak Period (Max)	120	Sec
Flux Soak Temp (Min)	150	°C
Flux Soak Temp (max)	190	°C
Time Above Liquidous (max)	70	Sec
Time Above Liquidous (min)	50	Sec
Time In Target Reflow Range (goal)	30	Sec
Time At Absolute Peak (max)	5	Sec
Liquidous Temperature (SAC305)	218	°C
Lower Target Reflow Temperature	240	°C
Upper Target Reflow Temperature	250	°C
Absolute Peak Temperature	260	°C

9 REGULATORY

Note: For complete regulatory information, refer to the [BL654 Regulatory Information](#) document which is also available from the [BL654 product page](#).

The BL654 holds current certifications in the following countries:

Country/Region	Regulatory ID
USA (FCC)	SQGBL654
EU	N/A
Canada (ISED)	3147A-BL654
Japan (MIC)	201-180112
Australia	N/A
New Zealand	N/A

10 ORDERING INFORMATION

Part Number	Product Description
451-00001	Bluetooth v5/802.15.4/NFC module – Integrated antenna
451-00002	Bluetooth v5 / 802.15.4 / NFC module – External antenna
451-00003	Intelligent USB Bluetooth v5 adapter
455-00001	Development Kit for 451-00001 module – Integrated antenna
455-00002	Development Kit for the 451-00002 module – External antenna
451-00001C	Bluetooth v5/802.15.4/NFC module – Integrated antenna – Cut/Tape
451-00002C	Bluetooth v5 / 802.15.4 / NFC module – External antenna – Cut/Tape

11 BLUETOOTH SIG QUALIFICATION

11.1 Overview

The BL654 module is listed on the Bluetooth SIG website as a qualified End Product.

Design Name	BT Version	Owner	Declaration ID	QD ID	Link to listing on the SIG website
BL654	5.0	Laird Connectivity	D040166	114304	https://launchstudio.bluetooth.com/ListingDetails/63185
BL654	5.0	Laird Connectivity	D041400	117615	https://launchstudio.bluetooth.com/ListingDetails/67595
BL654	5.1	Laird Connectivity	D049255	145177	https://launchstudio.bluetooth.com/ListingDetails/102275
BL654	5.3	Laird Connectivity	D057230	194918	https://launchstudio.bluetooth.com/ListingDetails/163217

It is a mandatory requirement of the Bluetooth Special Interest Group (SIG) that every product implementing Bluetooth technology has a Declaration ID. Every Bluetooth design is required to go through the qualification process, even when referencing a Bluetooth Design that already has its own Declaration ID. The Qualification Process requires each company to register as a member of the Bluetooth SIG – www.bluetooth.org

The following link provides a link to the Bluetooth Registration page: <https://www.bluetooth.org/login/register/>

For each Bluetooth Design, it is necessary to purchase a Declaration ID. This can be done before starting the new qualification, either through invoicing or credit card payment. The fees for the Declaration ID will depend on your membership status, please refer to the following webpage:

<https://www.bluetooth.org/en-us/test-qualification/qualification-overview/fees>

For a detailed procedure of how to obtain a new Declaration ID for your design, please refer to the following SIG document:

https://www.bluetooth.org/DocMan/handlers/DownloadDoc.ashx?doc_id=283698&vld=317486

11.2 Qualification Steps When Referencing a Laird Connectivity End Product Design

To start a listing, go to: https://www.bluetooth.org/tpg/QLI_SDoc.cfm

In step 1, select the option, **Reference a Qualified Design** and enter D040166, D041400, D049255, or D057230 in the End Product table entry. You can then select your pre-paid Declaration ID from the drop-down menu or go to the Purchase Declaration ID page, (please note that unless the Declaration ID is pre-paid or purchased with a credit card, it will not be possible to proceed until the SIG invoice is paid).

Once all the relevant sections of step 1 are finished, complete steps 2, 3, and 4 as described in the help document. Your new Design will be listed on the SIG website and you can print your Certificate and Declaration of Conformity.

For further information, please refer to the following training material:

<https://www.bluetooth.org/en-us/test-qualification/qualification-overview/listing-process-updates>

Note: If using the BL654 with Laird Connectivity Firmware and *smartBASIC* script, you can skip “Controller Subsystem”, “Host Subsystem”, and “Profile Subsystem”.

11.3 Qualification Steps When Deviating from a Laird Connectivity End Product Design

If you wish to deviate from the standard End Product design listed under D040166, D041400, D049255, or D057230, the qualification process follows the Traditional Project route, creating a new design. When creating a new design, it is necessary to complete the full qualification listing process and also maintain a compliance folder for the new design.

The BL654 design under D040166 incorporates the following components:

Listing reference	Design Name	Core Spec Version
D038622	S140 Host v6.0.0	5.0
D038623	S140 Link layer v6.0.0	5.0

The BL654 design under D041400 incorporates the following components:

Listing reference	Design Name	Core Spec Version
D039780	S140 Host v6.1.0	5.0
D040756	S140 Link layer v6.1.0x	5.0

The BL654 design under D049255 incorporates the following components:

Listing reference	Design Name	Core Spec Version
D043345	S140 SoftDevice Link Layer v7.0.1	5.1
D043346	S140 Host Layer v7.0.1	5.1

In the future, Nordic may list updated versions of these components and it is possible to use them in your new design. Please check with Nordic to make sure these software components are compatible with the nRF52 hardware XXXXX

If your design is based on un-modified BL654 hardware it is possible use the following process;

1. Reference the existing RF-PHY test report from the BL654 listing.

2. Combine the relevant Nordic Link Layer (LL) – check QDID with Nordic.
3. Combine in a Host Component (covering L2CAP, GAP, ATT, GATT, SM) - check QDID with Nordic.
4. Test any standard SIG profiles that are supported in the design (customs profiles are exempt).

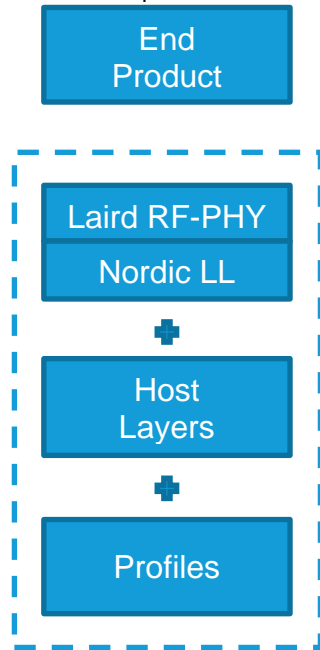


Figure 27: Scope of the qualification for an End Product Design

The first step is to generate a project on the TPG (Test Plan Generator) system. This determines which test cases apply to demonstrate compliance with the Bluetooth Test Specifications. If you are combining pre-tested and qualified components in your design and they are within their three-year listing period, you are not required to re-test those layers covered by these components.

If the design incorporates any standard SIG LE profiles (such as Heart Rate Profile), it is necessary to test these profiles using PTS or other tools where permitted; the results are added to the compliance folder.

You are required to upload your test declaration and test reports (where applicable) and then complete the final listing steps on the SIG website. Remember to purchase your Declaration ID before you start the qualification process, as it's impossible to complete the listing without it.

For the BL654 the design under D057230, it is based on Subsystem combination and not from Tested Components, refer to the table below:

Listing reference	Design Name	Core Spec Version
D060226	nRF Connect SDK Host Subsystem	5.3
D060225	Zephyr™ OS Controller for nRF Connect SDK v2.1.0	5.3

If you change any of the referenced Subsystems in your design, it will be necessary to qualify the new combination. In Launch Studio select the 'Start the Bluetooth Qualification Process with **No Required Testing**' and enter the subsystem references for your new design.

Complete the 'Product Declaration' tab on Launch Studio, adding your listing date and all End Products that use your Bluetooth design.

For each Bluetooth Design, it is necessary to purchase a Declaration ID. This can be done before starting the new qualification, either through invoicing or credit card payment. The fees for the Declaration ID will depend on your membership status, please refer to the following webpage:

<https://www.bluetooth.org/en-us/test-qualification/qualification-overview/fees>

For a detailed procedure of how to obtain a new Declaration ID for your design, please refer to the following SIG document:

https://www.bluetooth.org/DocMan/handlers/DownloadDoc.ashx?doc_id=283698&vld=317486

Select your purchased Declaration ID on the 'Declaration ID' tab and then proceed to the 'Review and Submit' tab. Launch Studio will perform some system checks and make sure all mandatory items have been completed. Three green ticks will be displayed if everything is correct, or the system will flag up any errors that must be fixed before you can complete the design listing.

Follow the steps to complete the listing, once listed download a copy of the SDoC and place a copy in your compliance folder.

12 RELIABILITY TESTS

The BL654 module went through the below reliability tests and passed.

Test Sequence	Test Item	Test Limits and Pass	Test Conditions
1	Vibration Test	JESD22-B103B Vibration, Variable frequency	Sample: Unpowered. Sample number: 3. Vibration waveform: Sine waveform. Vibration frequency /Displacement: 20 to 80Hz /1.52mm. Vibration frequency /Acceleration: 80 to 2000Hz /20g. Cycle time: 4 minutes. Number of cycles: 4 cycles for each axis. Vibration axis: X, Y and Z (Rotating each axis on vertical vibration table).
2	Mechanical Shock	JESD22-B104C	Sample: Unpowered. Sample number: 3. Pulse shape: Half-sine waveform. Impact acceleration: 1500g. Pulse duration: 0.5ms. Number of shocks: 30 shocks (5 shocks for each face). Orientation: Bottom, top, left, right, front and rear faces.
3	Thermal Shock	JESD22-A104E Temperature cycling	Sample: Unpowered. Sample number: 3. Temperature transition time: Less than 30 seconds. Temperature cycle: -40°C (10 minutes), +85 °C (10 minutes). Number of cycles: 350.

Before and after the testing, visual inspection showed no physical defect on samples.

After Vibration test and Mechanical Shock testing, the samples were functionally tested, and all samples functioned as normal. Then after Thermal shock test, the samples were functionally tested, and all samples functioned as normal.

13 ADDITIONAL INFORMATION

Please contact your local sales representative or our support team for further assistance:

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Sales Contact	www.lairdconnect.com/contact

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